

SIITME 2026

CONFERENCE & EXHIBITION

28th - 31st October 2026, Târgoviște, Romania

32nd
edition

IEEE

International Symposium
for Design and Technology in
Electronics Packaging



Indexed by:
IEEE Xplore®



ELSEVIER
Scopus

Organized by:

	National University of Science and Technology POLITEHNICA Bucharest, Romania http://www.upb.ro Faculty of Electronics, Telecommunications and Information Technology https://etti.upb.ro/en/
	Valahia University of Târgoviște, Romania https://www.valahia.ro/en/ Faculty of Electrical Engineering, Electronics and Information Technology http://fie.valahia.ro/
	Institute of Multidisciplinary Research for Science and Technology (ICSTM) https://icstm.ro/
	Technical University of Cluj Napoca Faculty of Electronics, Telecommunications and Information Technology https://www.utcluj.ro
	Association for Promoting Electronics Technology, APTE http://www.apte.org.ro
	Center for Technological Electronics and Interconnection Techniques http://www.cetti.ro
	and supported by: EPETRUM (Electronics Packaging Education Training and Research University Network)

EDITORS: Paul Svasta, Cristina Marghescu, Delia Lepădatu, Cătălina Neghină
DTP: Bogdan Mihăilescu
Publisher:

SIITME 2026

IEEE 32nd INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONICS PACKAGING

- CONFERENCE AND EXHIBITION -

October 28th – 31st, 2026

Târgoviște, Romania

Valahia University of Târgoviște

Table of Contents

WELCOME TO THE IEEE 32ND SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONICS PACKAGING!	1
SIITME 2026 AGENDA	5
Workshop “Generational Dialogue: Education, Industry, and Artificial Intelligence”	7
SIITME History	8
Keynote Speakers	10
Program in detail	15
SIITME 2026 Committees	34
SIITME 2026 Reviewers	36
SIITME 2026 Posters Assessor Committee	37
Industry	38
Research	51
Cluj-Napoca welcomes to the IEEE 33 rd International Symposium for Design and Technology in Electronics Packaging!	58

Welcome to the IEEE 32nd Symposium for Design and Technology in Electronics Packaging!

It is our great pleasure to welcome you to the 32nd edition of SIITME – the IEEE International Symposium for Design and Technology in Electronic Packaging, held in Târgoviște, Romania, in 2026.

Since its establishment in 1995, SIITME has become a well-respected international forum bringing together researchers, educators, industry professionals, and students who share a common interest in electronic packaging, manufacturing technologies, reliability, materials, and emerging electronic systems. Over more than three decades, the symposium has fostered collaboration between academia and industry, encouraging innovation and the exchange of ideas across disciplinary and geographical boundaries.

SIITME 2026 continues this tradition by providing a dynamic platform for presenting and discussing the latest scientific and technological developments in the field. The symposium offers an engaging program featuring:

- Plenary lectures delivered by distinguished experts from academia and industry
- Technical sessions presenting recent advances in research and development
- Poster sessions highlighting innovative projects and emerging topics
- Industrial exhibitions and networking opportunities
- Professional development activities for students, young researchers, and practicing engineers

This year's edition is hosted in the historic city of Târgoviște. We hope that beyond the technical program, participants will enjoy the opportunity to discover the city's rich heritage, traditions, and hospitality.

We would like to express our sincere gratitude to the local organizing committee, the members of the Technical Program Committee, our sponsors, partners, and volunteers, whose dedication and support have made SIITME 2026 possible. Their commitment to advancing education, research, and innovation in electronics continues to strengthen our community year after year.

Whether you are joining us to present your work, learn about the latest developments, establish new collaborations, or reconnect with colleagues and friends, we hope that SIITME 2026 will provide an inspiring and rewarding experience for all participants.

Welcome to SIITME 2026. Welcome to Târgoviște.



Prof. D.H.C. mult. Paul SVASTA, Ph.D.
IEEE Life Fellow

SIITME 2026 General Chair
National University of Science and
Technology POLITEHNICA of Bucharest,
APTE-Association for Promoting
Electronics Technology



Prof. Ovidiu A. POP, Ph.D.

SIITME 2026 General Co-Chair
Dean of Faculty of Electronics,
Telecommunications and Information
Technology, Technical University of Cluj-
Napoca

Dear participants and guests,

It is my great pleasure to welcome you to Târgoviște, for the 2026 edition of the SIITME (EEE 32st International Symposium for Design and Technology in Electronic Packaging), hosted by Valahia University of Târgoviște. On behalf of the Faculty of Electrical Engineering, Electronics and Information Technology, I am honored to welcome researchers, academics, engineers, and industry professionals from around the world to this important scientific event.

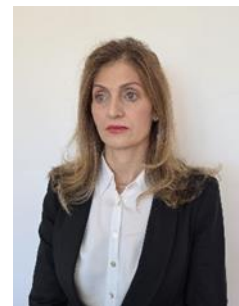
In a time of rapid technological development, the fields of electronics and electronic packaging continue to create new opportunities while addressing complex scientific and industrial challenges. SIITME provides a valuable platform for sharing research results, exchanging innovative ideas, and fostering collaboration between academia and industry.

We are proud to host this prestigious symposium at Valahia University of Târgoviște and to contribute to the advancement of scientific knowledge, technological innovation, and international academic cooperation. We believe that the exchange of expertise and perspectives among participants will inspire new research directions and lasting professional partnerships.

We also hope that your visit will offer you the opportunity to discover the rich history, cultural heritage, and hospitality of Târgoviște and to enjoy your stay.

I would like to express my sincere appreciation to the organizing and scientific committees, IEEE, our partners, and all those whose dedication and commitment have contributed to making SIITME 2026 possible.

Associate professor, Nicoleta ANGELESCU Ph. D
SIITME 2026 Conference Chair
Dean of Faculty of Electrical Engineering, Electronics and
Information Technology
Valahia University of Târgoviște



Message from the Institute for Multidisciplinary Scientific and Technological Research

It is a pleasure and an honour for the Institute for Multidisciplinary Scientific and Technological Research (ICSTM) of Valahia University of Târgoviște to be among the partners of the 32nd edition of the IEEE International Symposium for Design and Technology in Electronic Packaging (SIITME 2026) this year. The fact that a symposium with such a rich tradition—founded in 1995 at the University POLITEHNICA of Bucharest and growing, edition after edition, across major university centres in Romania and Hungary—has now arrived in Târgoviște fills us with both gratitude and a sense of responsibility.

Over the course of three decades, SIITME has achieved something few scientific events manage to do: it has remained true to its core field, electronic packaging, while also embracing everything this field has grown to encompass, from nanomaterials and printed electronics to embedded systems, artificial intelligence, renewable energy, and reliability. This is precisely the kind of dialogue between disciplines that ICSTM fosters every day in its laboratories, through teams working at the intersection of engineering sciences, materials, the environment, and digital technologies.

For the researchers at our institute, the symposium's four days represent more than an event hosted here: they are a rare opportunity to exchange ideas with an outstanding international community, build lasting collaborations, and demonstrate what multidisciplinary research in Târgoviște can achieve. We are especially pleased to welcome students and doctoral candidates from IEEE chapters, as they are the ones who will carry this tradition forward.

I would like to thank the organisers, the Professional Association of Electronics Technologists and the IEEE Hungary & Romania EPS&NTC Joint Chapter, for placing their trust in our university. I wish all participants productive sessions, inspiring discussions, and enjoyable days in a city that was, for centuries, the heart of Wallachia.

Welcome to Târgoviște!

Prof. Gabriel CROITORU, PhD, Habil.
Director of ICSTM
Valahia University of Târgoviște



SIITME 2026 Agenda

Wednesday, October 28

09:30 – 11:00	Arrival, registration
11:00 – 12:30	Workshop: Generational Dialogue: Education, Industry, and Artificial Intelligence
12:45 – 14:15	Lunch Break
14:15 – 14:30	SIITME 2026 Opening ceremony
14:30 – 16:15	Plenary Oral Session 1, Keynote presentation: Attila BONYAR, BME Hungary
16:15 – 16:30	Coffee break
16:30 – 17:30	Industrial Session 1
18:30 – 20:30	Welcome to SIITME dinner - Hotel Del Ponte
20:30 –	IEEE – Hu&Ro EPS&NTC Joint Chapter Meeting – members & IEEE guests

Thursday, October 29

09:00 – 13:30	Registration / Welcome coffee
09:00 – 11:00	Plenary Oral Session 2, Keynote presentation: Cristina DRĂGAN, AUMOVIO Timișoara, Romania
11:00 – 11:15	Coffee break
11:15 – 12:45	Poster Session 1
12:45 – 13:45	Conference Lunch
13:45 – 14:30	Industrial Session 2
14:30 – 16:00	Poster Session 2
16:15 – 19:00	Cultural Program
19:00 –	Conference dinner - Hotel Del Ponte

Friday, October 30

09:00 – 11:00	Plenary Oral Session 3, Keynotes presentations: Boris ESTATIEV - University of Ruse Angel Kanchev, Bulgaria, Cătălin CIOBANU - Transilvania University of Brașov, Romania
11:00 – 11:15	Coffee Break
11:15 – 12:45	Poster Session 3
12:45 – 13:45	Conference Lunch
13:45 – 15:45	Plenary Oral Session 4 – Online, Keynote presentation: Mihai GABOR - Technical University of Cluj-Napoca, Romania
15:45 – 17:10	Poster Session 4
17:10 – 17:30	Coffee Break
17:30 – 18:30	Steering Committee Meeting
18:30 – 19:30	Awarding ceremony; Welcome to SIITME 2027
19:30 – 22:00	Dinner - Hotel Del Ponte

Saturday, October 31

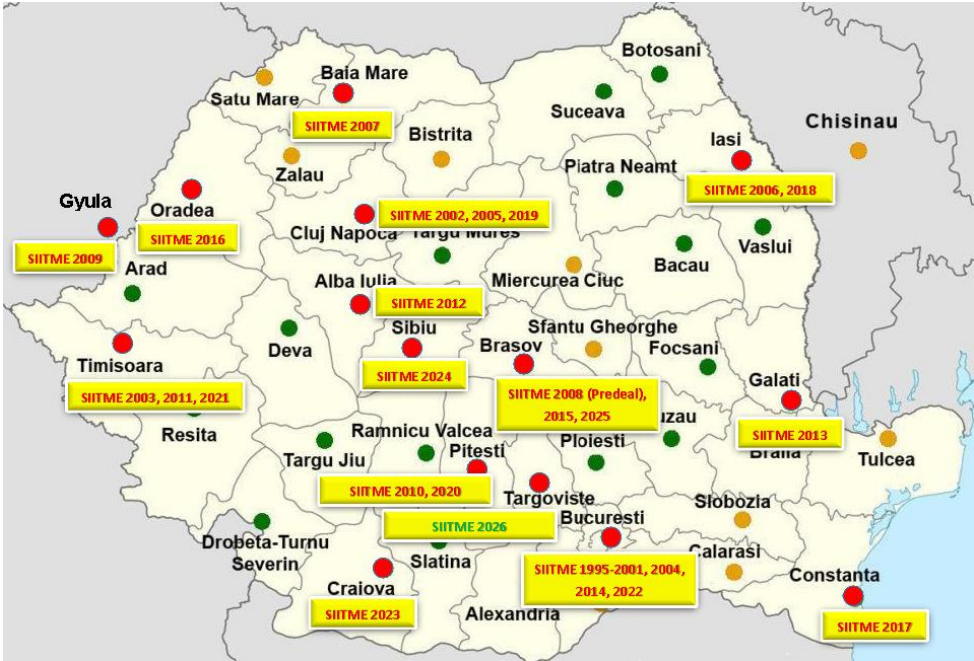
09:00 – 11:00	Event retrospective
---------------	---------------------

Intentionally left blank

Workshop “Generational Dialogue: Education, Industry, and Artificial Intelligence”

Time Interval	Activity
11:00–11:05	Opening and objectives
11:05–11:15	What industry expects from graduates
11:15–11:25	What education offers and how it can collaborate with industry
11:25–11:35	AI and the start of a career: Opportunities, risks, and essential skills
11:35–12:20	Intergenerational panel
12:20–12:30	Conclusions and action steps

SIITME History



SIITME 1995, CAE-CAD-CAM Technologies in Electronic Modules Design, UPB, Bucharest, Romania

SIITME 1996, The 2nd International Seminar for Informatics and Technology in the domain of Electronic modules, 23-24 October 1996, Bucharest, Romania

SIITME 1997, The 3rd International Seminar for Informatics and Technology in the domain of Electronic modules, 22-23 October 1997, Bucharest, Romania

SIITME 1998, The 4th International Symposium for Informatics and Technology in Electronic Modules Domain, September 22-24 1998, Bucharest, Romania

SIITME 1999, The 5th International Symposium for Design and Technology in Electronic Modules, September 23-26 1999, Bucharest, Romania

SIITME 2000, The 6th International Symposium for Design and Technology for Electronic Modules, September 21-24, 2000, Bucharest, Romania

SIITME 2001, The 7th International Symposium for Design and Technology of Electronic Modules, September 20-23, 2001, Bucharest, Romania

SIITME 2002, The 8th International Symposium for Design and Technology of Electronic Modules, September 19-22, 2002, Cluj-Napoca, Romania

SIITME 2003, The 9th International Symposium for Design and Technology of Electronic Packages, September 18-21, 2003, Timișoara, Romania

SIITME 2004, The 10th International Symposium for Design and Technology for Electronic Modules, September 23-26 2004, Bucharest, Romania

SIITME 2005, International Symposium for Design and Technology of Electronic Packaging, 11th Edition, September 22-25, 2005, Cluj-Napoca, Romania

SIITME 2006, International Symposium for Design and Technology of Electronic Packaging, 12th Edition, September 21-24, 2006, Iași, Romania

SIITME 2007, International Symposium for Design and Technology of Electronic Packaging, 13th Edition, September 20-23, 2007, Baia Mare, Romania

SIITME 2008, International Symposium for Design and Technology of Electronic Packaging, 14th Edition, September 18-21, 2008, Predeal, Romania

SIITME 2009, 15th International Symposium for Design and Technology of Electronic Packaging, 17-20 September 2009, Gyula, Hungary

SIITME 2010, 16th International Symposium for Design and Technology in Electronic Packaging, September 23-26, 2010, Pitești, Romania.

SIITME 2011, IEEE 17th International Symposium for Design and Technology in Electronic Packaging, October 20-23, 2011, Timișoara, Romania.

SIITME 2012, IEEE 18th International Symposium for Design and Technology in Electronic Packaging, Alba Iulia, Romania

SIITME 2013, IEEE 19th International Symposium for Design and Technology in Electronic Packaging, Galați, Romania

SIITME 2014, IEEE 20th International Symposium for Design and Technology in Electronic Packaging, October 23–26, 2014, Bucharest, Romania

SIITME 2015, IEEE 21st International Symposium for Design and Technology in Electronic Packaging, October 22-25, 2015, Brașov, Romania

SIITME 2016, IEEE 22nd International Symposium for Design and Technology in Electronic Packaging, October 20-23, 2016, Oradea, Romania

SIITME 2017, IEEE 23rd International Symposium for Design and Technology in Electronic Packaging - October 26-29, 2017, Constanta, Romania

SIITME 2018, IEEE 24th International Symposium for Design and Technology in Electronic Packaging - October 25–28, 2018, Iași, Romania

SIITME 2019, IEEE 25th International Symposium for Design and Technology in Electronic Packaging - October 23–26, 2019, Cluj-Napoca, Romania

SIITME 2020, IEEE 26th International Symposium for Design and Technology in Electronic Packaging - October 21–24, 2020, Pitești, Romania – On-line edition

SIITME 2021, IEEE 27th International Symposium for Design and Technology in Electronic Packaging - October 27–29, 2021, Timișoara, Romania – On-line edition

SIITME 2022, IEEE 28th International Symposium for Design and Technology in Electronic Packaging, October 26–29, 2022, Bucharest, Romania

SIITME 2023, IEEE 29th International Symposium for Design and Technology in Electronics Packaging - Conference and Exhibition, October, 18 – 21, 2023, Craiova, Romania

SIITME 2024, IEEE 30th International Symposium for Design and Technology in Electronic Packaging - SIITME 2024, Sibiu, Romania

SIITME 2025, IEEE 31st International Symposium for Design and Technology in Electronic Packaging - SIITME 2025, Brașov, Romania

Keynote Speakers



Name: Attila BONYÁR

Job position: Professor

Company: Budapest University of Technology and Economics, Department of Electronics Technology

e-mail: bonyar.attila@vik.bme.hu

Presentation: “Recent Advances in Plasmonic Interconnect Technologies”

Attila Bonyár is a full professor, vice head of department and head of the Nanotechnology and Sensorics Research Group at the Department of Electronics Technology, Faculty of Electronics Engineering and Informatics, Budapest University of Technology and Economics. He is an elected member of the Hungarian Academy of Sciences (HAS) General Assembly. He has been a senior IEEE member since 2021 and actively serves in several IEEE committees. In 2025, he received the EUROSENSORS Fellow award. His activities focus on developing optical biosensor technologies that utilize plasmonics and nanomaterials.

Abstract

Several issues that prevent significant increases in processor performance can be traced to thermal and signal-delay effects associated with electronic interconnects. While optical interconnects might offer solutions to these problems, the size mismatch relative to electronic interconnects prevents their convenient co-integration. Plasmonics is gaining increasing attention as a possible solution to overcome these bandwidth limitations by combining the advantageous properties of both classical electronic and advanced optical interconnects. Surface plasmon polaritons (SPPs) are collective electron oscillations excited by and coupled with electromagnetic waves at the boundary of a material with negative permittivity (traditionally metals) and an insulator with positive permittivity. In plasmonic interconnects, SPPs transport information at the interface between two materials at ultrafast speeds while offering sub-wavelength resolution. While SPP-based interconnects can reduce signal delay, their main disadvantage is the high propagation losses, which limit the achievable interconnect lengths. Losses in tightly confined plasmonic systems also force a trade-off between energy per bit and interconnect density. To tackle these challenges, many new material systems and fabrication technologies have emerged in the past decade. In addition to classical metallic thin-film-based plasmonic waveguides, interconnects have been fabricated from transition-metal nitrides or two-dimensional materials. The talk will introduce plasmonic interconnects and the challenges hindering their applicability, focusing on recent advances, novel material systems, and nanofabrication technologies to solve these issues.



Name: Cristina Mihaela DRĂGAN

Job position: Thermal Analyst Expert

Company: AUMOVIO Timișoara

e-mail: cristina-mihaela.dragan@aumovio.com

Presentation: “Thermal Evaluation of Heat Generating Components in Automotive High-Performance Computing (HPC) Units”

Cristina Mihaela Drăgan, PhD — Thermal Architect at AUMOVIO (Continental Automotive), Timișoara, Romania — Qualification Labs Technologies Thermal Simulation and Verification (QL TSV).

With over 16 years of experience in automotive thermal management, she has held key roles at Continental Automotive ADAS (2008–2022), Infineon Technologies as Thermal Solution Consultant (2022–2023), and Continental Software and Central Technologies SCT (2023–2024). Her expertise spans system-to-silicon thermal design for high-performance computing (HPC) units, simulation-to-test correlation, and thermal reliability of electronic systems. Driven by a constant desire to explore new thermal solution technologies, she has also focused on Design for Six Sigma (DfSS), applying it to optimize thermal behavior in automotive products. She has strong knowledge in passive cooling optimization and in fan-cooling, liquid-cooling, heat-pipe, and Peltier solutions - along with their technical limitations.

Abstract

This presentation challenges the common assumption that higher power means higher temperature. Through a systematic analysis of real HPC automotive components, it demonstrates that power density, relative cooling solution, and package thermal resistances (R_{thJC} , R_{thJB}) are stronger drivers of junction temperature than absolute power dissipation. A Design of Experiments (DoE) approach with Pareto charts ranks these parameters for both self-heating and safety margin, revealing that critical components can be easily overlooked without comprehensive analysis. The talk introduces a system-to-silicon framework spanning SW, electronic, and mechanical design disciplines, highlights the growing tension between performance increase, cost reduction, and harsher environment conditions, and defines the key attributes of a thermally reliable product.



Name: Boris EVSTATIEV
Job position: Professor
Company: Angel Kanchev University of Ruse
e-mail: bevstatiev@uni-ruse.bg
Presentation: **“Research and Engineering Education in the Age of AI: Opportunities, Boundaries, and Principles”**

Boris I. Evstatiev is a Full Professor in Electronics and Lead Researcher of the Laboratory “Digital Energy Systems 4.0” at the Angel Kanchev University of Ruse, Ruse, Bulgaria. He received his MSc in Computer Technologies in 2005, PhD in Mechanization and Electrification of Animal Husbandry in 2009, and DSc in Automation of Intangible Areas in 2022, all from the University of Ruse. His research interests include the Internet of Things, data analysis, renewable energy systems, machine learning, and related areas. Prof. Evstatiev also serves as Technical Program Committee Chair of the IEEE Conference on Energy Efficiency and Agricultural Engineering.

Abstract

The rapid development of artificial intelligence (AI) is transforming virtually every sphere of human activity, including science and engineering education. Its growing integration into these fields raises not only questions about efficiency and productivity, but also fundamental questions about ethics, reliability, and the role of human expertise. In scientific research, AI can support a wide range of activities related to data analysis, forecasting, classification, etc., driven primarily by the quality and reliability of the obtained results; however, using AI during the dissemination phases raises many concerns. Similar challenges arise in engineering education, where generative AI tools have the potential to increase the efficiency of both educators and teachers, as long as appropriate limitations are defined regarding their application. This presentation explores the opportunities and limitations of AI in research and engineering education, with particular focus on identifying the boundary between acceptable and unacceptable use. It aims to point out the basic principles of AI integration in the educational process required for creating the future engineers.



Name: Cătălin CIOBANU

Job position: Associate Professor /
Senior Researcher

Company: Transilvania University of Brasov /
National Institute for Research and
Development in Microtechnologies
- IMT Bucharest

e-mail: catalin.ciobanu@unitbv.ro
catalin.ciobanu@imt.ro

Presentation: "ISOLDE: Building Blocks for High-
Performance RISC-V Systems"

Cătălin CIOBANU has a MSc and PhD from Delft University of Technology, The Netherlands. He is currently Associate Professor at Transilvania University of Brasov, Romania and Senior Researcher at the National Institute for Research and Development in Microtechnologies - IMT Bucharest, Romania. His research interests include RISC-V processors, embedded systems, high-performance computing, SIMD architectures, digital signal processing and reconfigurable hardware.

Abstract

The pursuit for technological sovereignty is a cornerstone of the European industrial strategy. A key element in this endeavor is the availability of high-performance yet still energy-efficient computing resources. To prevent long-term vendor lock-in and reduce critical dependence on proprietary Intellectual Property (IP), the European Union is pivoting towards open-source solutions. A transparent, flexible, and strong ecosystem around RISC-V is essential, and key European actors from academia and industry are working together to create a unified hardware-software design environment that enables customization and optimization for various application classes. Fully in line with these European strategic goals is the Chips Joint Undertaking (Chips-JU)-funded project ISOLDE (High Performance, Safe, Secure, Open-Source Leveraged RISC-V Domain-Specific Ecosystems). Launched in 2023, ISOLDE expands this hardware ecosystem to the application level. It targets the delivery of industrial-grade open-source hardware and software for complex SoCs. This includes a focus on high-performance superscalar and 64-bit cores with out-of-order execution (centered around CVA6 and NOEL-V) as well as specialized hardware accelerators.



Name: Mihai Sebastian GABOR

Job position: Associate Professor

Company: Technical University of Cluj-Napoca

e-mail: mihai.gabor@phys.utcluj.ro

Presentation: “Spin-Orbitronics: Principles, Materials and Devices”

Mihai Sebastian Gabor, PhD, Dr. Habil., is an Associate Professor at the Technical University of Cluj-Napoca (TUCN), where he leads the spintronics and spin-orbitronics research direction of the Center for Superconductivity, Spintronics and Surface Science (C4S). He received a joint PhD in Physics and Materials Engineering from Université Henri Poincaré, Nancy (France) and TUCN in 2011, and was awarded the habilitation in Materials Engineering in 2025 (thesis: Materials for Spin-Orbitronics). His research covers the growth of ultrathin magnetic heterostructures, spin-orbit torques, perpendicular magnetic anisotropy, the interfacial Dzyaloshinskii–Moriya interaction, and chiral domain-wall and skyrmion devices for memory, logic and neuromorphic computing. He has led five national research projects and has co-authored nearly 100 journal articles (Google Scholar h-index 27). He has been an invited researcher at SPINTEC-CEA Grenoble and an invited professor at Université Paris 13.

Abstract

Spin-orbitronics uses spin-orbit coupling in heavy metals and at interfaces to switch or move magnetization electrically with pure spin currents, making it a strong candidate for fast, non-volatile and energy-efficient memory, logic and neuromorphic hardware. This talk reviews the spin Hall effect, spin-orbit torques and the interfacial Dzyaloshinskii–Moriya interaction, and the materials requirements they set for heavy-metal/ferromagnet/oxide heterostructures: strong perpendicular magnetic anisotropy, efficient charge-to-spin conversion and controlled magnetic chirality. Using examples from ultrathin Pt/Co/MgO and Heusler-alloy films grown at C4S/TUCN, it illustrates how atomic-scale interface engineering tunes these properties and the current-driven dynamics of chiral domain walls and skyrmions. It then presents device functionalities built on these effects, including magnetic domain-wall diodes and routers and field-free spin-orbit torque elements for artificial synapses and neurons. The talk concludes with perspectives on voltage-gated control of spin-orbit effects and on integrating spin-orbitronic devices with conventional electronics.

*Program in detail***Wednesday, October 28****14:15 – 14:30**
EEST | GMT +3h**Opening ceremony SIITME 2026****Paul SVASTA**, *SIITME 2026 General Chair, POLITEHNICA Bucharest, Romania***Daniel Emil Constantin DUNEA**, *Vice-Rector for University Research and Creation, Valahia University of Târgoviște, Romania***14:30 – 16:15**
EEST | GMT +3h**Plenary Oral Session 1****Session Chair:** Nicoleta ANGELESCU, Valahia University of Târgoviște, Romania**Session Co-Chair:** Paul SVASTA, National University of Science and Technology POLITEHNICA of Bucharest, Romania**K1 Recent Advances in Plasmonic Interconnect Technologies****Attila BONYAR**

Professor, BME Hungary

O1.1 ID130 From Predictive AI to Agentic Closed-Loop Optimization: A Structured Review of AI-EDA

V. Șerban, I. Elisei, M. Tolontan, C. Orhei

Faculty of Electronics, Telecommunications and Information Technologies, Politehnica University Timișoara, Timișoara, Romania

O1.2 ID136 Signal Processing Optimization for LSPR Nanosensors Using a Custom Imaging-Based Optical SystemD. Kaouari, T. Lednický¹, L. T. Csőke², and A. Bonyár

Department of Electronics Technology, Faculty of Electrical Engineering and Informatics, Budapest University of Technology and Economics, Budapest, Hungary

¹ Leibniz Institute of Photonic Technology, Jena, Germany² Optimal Optik Ltd., Budapest, Hungary**O1.3 ID108 A Methodology for PCBA Fault Diagnosis Using Infrared Thermography and Machine Learning**S. Dimitrov¹, D.-S. Vizitiu², R.-N. Susanu², R.-G. Ailiesei², S. Kadirova¹, B. Evstatiev¹¹ Department of Automatics & Electronics, Angel Kanchev University of Ruse, Ruse, Bulgaria² Department of Telecommunications and Information Technologies, Gheorghe Asachi Technical University of Iasi, Iasi, Romania

16:30 – 17:30 **Industrial Session 1**
EEST | GMT +3h

Session Chair: Daniel-Ciprian VASILE, POLITEHNICA Bucharest, Romania

Session Co-Chair: Liviu OLTEANU, Valahia University of Târgoviște, Romania

AUMOVIO Technologies Romania

Bosch Engineering Center Cluj

Miele Tehnica Braşov

Thursday, October 29

09:00 - 11:00 **Plenary Oral Session 2**
EEST | GMT +3h

Session Chair: Arcadie CRACAN, Gheorghe Asachi Technical University of Iasi, Romania

Session Co-Chair: Boris EVSTATIEV, Angel Kanchev University of Ruse, Bulgaria

K2 Thermal Evaluation of Heat Generating Components in Automotive High-Performance Computing (HPC) Units

Cristina Mihaela DRĂGAN

Thermal Analyst Expert, AUMOVIO Timișoara

02.1 ID50 Non-Uniformity Correction in CMOS Image Sensors: A Review of Algorithms, Models, and Embedded Implementation

P. Dikulakov

Department of Automation and Electronics, Angel Kanchev University of Ruse, Ruse, Bulgaria

02.2 ID174 From Sensor Data to Vehicle Action: Causality-Aware Validation for Automotive IoT

A.A. Maftai, A. Lavric, A.I. Petrariu, M. Cenusă and V. Popa

Computers, Electronics and Automation Department, Stefan Cel Mare University of Suceava, Suceava, Romania

02.3 ID140 Error-Budget-Driven Behavioral Modeling and Design Specification of a CMOS Planar-Hall Magnetic Angle Sensor

G.I. Bonteanu, M.-L. Apostol, A. Cracan, and N. Patache

Fundamentals of Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Gheorghe Asachi Technical University of Iași, Iași, Romania

O2.4 ID85 Energy Management Algorithm in Smart Microgrids with Fuel Cells that Uses Battery Degradation Cost and Short-Term Load Prediction

T.M. Pătăraș, D. M. Petreus, E. Szilagyi, and D. Fodorean¹⁾

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

¹⁾ Electrical Machines and Drives, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

11:15 - 12:45 Poster Session 1 (Starts with a video pitching session in the plenary room, followed by discussion at the poster)

EEST | GMT +3h

Session Chair: Radu Gabriel BOZOMITU, Gheorghe Asachi Technical University of Iași, Romania

Session Co-Chair: Bálint MEDGYES, Budapest University of Technology and Economics, Hungary

P1.1 ID52 Delta-Based OTA Updates for Resource-Constrained AUTOSAR Classic ECUs

M.-R. Radu, and D. Petreus

Applied Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania,

P1.2 ID53 Comparative Evaluation of Adaptive Security Function Placement in Automotive Architectures

R. Radu, and D. Petreus

Applied Electronics Department, Faculty of Electronics, Telecommunications, and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.3 ID64 Overview of Automotive Safety, Cybersecurity and Standards for ADAS/ADS

D.-C. Gavrilescu, R. Fizesan, S. Pop, O. A. Pop

Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.4 ID71 Rapid Software Porting through Hardware-Software Co-Design and Heterogeneous Integration Technologies: A Comparative Analysis

G. Flutur¹⁾, A. I. Ilies²⁾, C. Corches¹⁾, and R. Jánó²⁾

¹⁾Automation Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

²⁾ Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.5 ID72 Transitioning to Edge AI for Automated Insect Pest Monitoring

C. Abramov, P. Svasta

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1.6 ID84 Wireless Hand Gesture Control System for a Mobile Platform

A. Catalan, R.-C. Constantinescu, and B. Alexandrescu

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1.7 ID90 Automatic Control System for Ventilation and Lighting Using Bluetooth Communication

L.-A. Pîrvu, R.-C. Constantinescu, and B. Alexandrescu

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1. 8 ID96 Monitoring the marine environment through advanced robotic detection using artificial intelligence mechanisms

T. Pintilie¹⁾, S. Segarceanu¹⁾, K. T. Hjelmervik²⁾ and G. Suciu¹⁾

¹⁾ BENE Cercetare S.R.L., Bucharest, Romania,

²⁾ Universitetet i Sørøst-Norge, Forskningsparken, Norway

P1.9 ID99 From GPUs to NPUs: A Survey on Accelerators

P. C. Mihalache, A. Bertescu ¹⁾, and C. B. Ciobanu^{1, 2)}

Electronics and Computers, Transilvania University of Braşov, Braşov, Romania

¹⁾ Electronics and Computers, Transilvania University of Braşov, Braşov, Romania

²⁾ Microtechnologies, National Institute of Research and Development, Bucharest, Romania

P1.10 ID103 Low-Cost Hardware-in-the-Loop Platform for Closed-Loop Stepper Motor Position Control Using LabVIEW

I. H. Baci, L. Viman, V. Bande, V. Veliciu and C. Onofrei

Applied Electronics Department

Technical University of Cluj Napoca, Cluj Napoca, Romania

P1.11 ID106 Intelligent MFA Control System in a Secure Environment using Edge AI and IoT

B.-M. Sărar, R.-C. Constantinescu, and B. Alexandrescu

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1.12 ID168 Crosstalk Reduction Between Adjacent Signal Traces Using Commercial EMI Suppressor Sheets

D. A. Antonovici, P. M. Svasta

Faculty of Electronics, Telecommunications and Information Technology, National University of Science and Technology POLITEHNICA Bucharest, Bucharest, Romania

P1.13 ID169 Jitter and Crosstalk Trade-offs of Serpentine Routing Geometries in 10 Gb/s Single-ended Interconnects

D. A. Antonovici, P. M. Svasta

Faculty of Electronics, Telecommunications and Information Technology, National University of Science and Technology POLITEHNICA Bucharest, Bucharest, Romania

P1.14 ID117 Hardware-Software Analyses with Prometheus for Raspberry Pi 5 Systems Optimization

A. Pușcașu, and T. C. Bălan

Faculty of Electrical Engineering and Computer Science, Transilvania University of Brașov, Brașov, Romania

P1.15 ID119 Timing Interference and Static Partitioning in Mixed-Criticality Systems: A QNX, Jailhouse, XtratuM and PikeOS Evaluation

A. Sas, G. Chindris, R. Fizesan, O.A. Pop

Department of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.16 ID120 Intelligent Automatic Number Plate Recognition System

M.-C. Andrei, R.-C. Constantinescu, and B. Alexandrescu

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1.17 ID124 Environmental Parameter Monitoring System in a Children's Playground

A.-M. Cristea, R.-C. Constantinescu, and B. Alexandrescu

Faculty of Electronics, Telecommunications & Information Technology National University of Science and Technology POLITEHNICA Bucharest, Romania

P1.18 ID137 Blind IoT Agent: A Local-First AI Assistant for Blind and Visually Impaired Users

D. Sabev, Ts. Kaneva, and I. Valova

Department of Computer Systems and Technologies, Angel Kanchev University of Ruse, Ruse, Bulgaria

P1.19 ID142 Applied Validation of Machine-Learning Intrusion Detection for Automotive ECUs

A.-M. Nica, and D. Petreuş

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.20 ID143 Federated Model Update Lifecycle for Automotive Intrusion Detection

A.-M. Nica, and D. Petreuş

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P1.21 ID145 Anti-tamper Conductive Mesh for SiP Devices

D. C. Vasile, P. M. Svasta, and R. C. Maxim

ETTI, National University of Science and Technology Politehnica Bucharest, Bucharest, Romania

P1.22 ID151 Securing the In-vehicle CAN bus Communication using AES Cryptography

N. Căldărar, L.-A. Perişoară

Faculty of Electronics, Telecommunications and Information Technology, National University of Science and Technology Politehnica Bucharest, Romania

P1.23 ID166 Neural Network Implementation for Keyword Spotting on Low-Cost Embedded HardwareD.-A. Uja^{1),2)}, P.-C. Medinceanu^{1),2)}, M. Enachescu^{1),2)}¹⁾ AMPLIPH Laboratory, CAMPUS Research Center,²⁾ National University of Science and Technology POLITEHNICA Bucharest, Romania**P1.24 ID167 Peltier-based Temperature Controlled Test System for Electronic Components**

A. Drumea, and C. I. Marghescu

Department of Electronics Technology and Reliability,

National University for Science and Technology Politehnica Bucharest, Romania

P1.25 ID172 AI-Based RF Spectrum Anomaly SensingA. Gutu, A. Lavric, A.-I. Petrariu, V. Popa, C. Patachia-Sultanoiu^{1),3)} and R. M. Mihai^{2),3)}

Computers, Electronics and Automation Department, Ştefan cel Mare University of Suceava, Suceava, Romania

¹⁾ Faculty of Electronics, Telecommunications and Information Technology, Technical University of Iasi Gheorghe Asachi, Iasi, Romania²⁾ Faculty of Electronics, Telecommunications and Information Technology, National University of Science and Technology Politehnica Bucharest, Bucharest, Romania³⁾ Orange Romania, Bucharest, Romania**P1.26 ID173 Drone Detection Using FMCW Radar and Range-Doppler Image Classification**G. Ungureanu, A. Lavric, A.-I. Petrariu, A.-A. Maftai, V. Popa, and R. M. Mihai^{1),2)}

Computers, Electronics and Automation Department, Ştefan cel Mare University of Suceava, Suceava, Romania

¹⁾ Faculty of Electronics, Telecommunications and Information Technology, National University of Science and Technology Politehnica Bucharest, Bucharest, Romania

²⁾ Orange Romania, Bucharest, Romania

13:45 – 14:30 Industrial Session 2

EEST | GMT +3h

Session Chair: Cristina – Mihaela NICOLESCU, Valahia University of Târgoviște, Romania

Session Co-Chair: Mădălin MOISE, National University of Science and Technology Politehnica Bucharest, Romania

RomTek Electronics

NXP Semiconductors

Rohde & Schwarz

14:30 - 16:00 Poster Session 2 (Starts with a video pitching session in the plenary room, followed by discussion at the poster)

EEST | GMT +3h

Session Chair: Gabriel CHINDRIȘ, Technical University of Cluj-Napoca, Romania

Session Co-Chair: Cătălin CIOBANU, Transilvania University of Brașov, Romania

P2.1 ID74 Impact of Package Interconnect Length on the Signal Integrity of a PCIe Gen6 Differential Channel

M. Olteanu, C. Davidaș, A. Grama and A. Tăut

Applied Electronics Department, Technical University of Cluj-Napoca, Romania

P2.2 ID93 Signal Integrity Comparison of Organic and Silicon Interposers

V. Veliciu²⁾, A. C. Popescu¹⁾, C. Onofrei²⁾, I. M. Burcea¹⁾, L. Viman²⁾

¹⁾ IEEE Nanotechnology Council Student Branch Chapter of POLITEHNICA Bucharest, NANO42, SBC63061A, National University of Science and Technology POLITEHNICA Bucharest, Bucharest, Romania

²⁾ IEEE Electronics Packaging Society Student Branch Chapter of Technical Univ. of Cluj-Napoca, EP21, SBC10228, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P2.3 ID131 Preliminary Performance Assessment of Power Distribution Networks in 2.5D Systems Based on Simplified SPICE Models

A. Cimpean, M. Daraban, and O. Pop

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P2.4 ID164A Reduced-Order Equivalent Circuit Model for a PEMFC Structure Based on Semiconductor Junction Characteristics

A. Terlea, A. Bojita and M. Purcar

Department of Electrotechnics and Measurements, Technical University of Cluj-Napoca, Cluj-Napoca, Cluj, Romania

P2.5 ID118 kt-fsv: An Open-Source Implementation and Reproducibility Audit of IEEE Std 1597.1-2022 Feature Selective Validation

R. Voina, M. Daraban, L. Viman and O. Pop

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P2.6 ID70 Design and Comparative Characterization of Positive and Negative Integrated Charge Pumps in BCD130Lite Gen2 Technology

A-L. Cretu, B. Marinca, A. Gontean

Microelectronics, Politehnica University Timisoara, Timisoara/Romania

P2.7 ID92 IoT Stethoscope: Design and Development of a Tool for Telemedicine

D. A. Circumariu, G. D. Şendrescu, S. D. Firincă

Department of Automatics and Electronics, University of Craiova, Craiova, Romania

P2.8 ID107 A Comparative Statistical Analysis of Motor Execution and Imagery EEG Signals Using Logarithmic Normalization

Ş. Gigo, And I. Neaga, D. Arălungăţ, G. Neagu

University of National Sciences and Technology Politehnica Bucharest, Bucharest

P2.9 ID114 Investigation of impact sensors and e-textile connectors for combatant suits

E. Visileanu¹⁾, A. G. Ene¹⁾, C. Jipa¹⁾, F. Dondea¹⁾, R. Herzog²⁾ and I. R. Radulescu¹⁾

¹⁾ The National R&D Institute for Textiles and Leather, Bucharest, Romania

²⁾ Micro Science SRL, Bucharest, Romania

P2.10 ID51 A Low-Complexity RLS Adaptive Algorithm with Variable Forgetting Factor

R. A. Otopoleanu^{1,2)}, C. L. Stanciu^{1,2)}, C. Paleologu¹⁾, and J. Benesty³⁾

¹⁾ Department of Telecommunications, POLITEHNICA Bucharest, Bucharest, Romania

²⁾ Academy of Romanian Scientists, Ilfov 3, 050044, Bucharest, Romania

³⁾ INRS-EMT, University of Quebec, Montreal, Canada

P2.11 ID54 Deterministic Cross-Simulator Pre-Validation for LoRaWAN ADR Benchmarking

A.-C. Puiu and O. A. Pop

Department of Applied Electronics Technical University of Cluj-Napoca Cluj-Napoca, Romania

P2.12 ID68 A Distributed Edge-to-Cloud Architecture for Embedded IoT Systems

Ș.-C. Tănăsescu¹⁾, C. B. Ciobanu^{1), 2)}

¹⁾Transilvania University of Brașov, Romania

²⁾National Institute of Research and Development in Microtechnologies, Bucharest, Romania

P2.13 ID94 Position Control of a CNC Machine Using a Hydrogen Fuel Cell-Based Power Architecture

I.-D. Roman

Automation Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P2.14 ID100 A New Software-Defined Radio System for M-QAM with Polyphase Filterbank-Based Symbol Timing Synchronization

R. G. Bozomitu, Ș. C. Stoica

Faculty of Electronics, Telecommunications and Information Technology, Gheorghe Asachi Technical University of Iași, Romania

P2.15 ID122 Towards Unified Soil Nitrogen Sensing via Alkaline Ammonia Volatilization and IoT Monitoring

G. Varzaru, R. Tulea, R. Ungurelu, V. Fatu¹⁾, and P. Svasta²⁾

Syswin Solutions, Bucharest, Romania

¹⁾ Research & Development Institute for Plant Protection, Bucharest/Romania

²⁾ National University for Science and Technology Politehnica, Bucharest, Romania

P2.16 ID129 Detection and Localization of Bluetooth Low Energy Devices

A. B. Andrieș, L. I. Petcu, A. M. Mazilu, D. Burdia, L. Scripcariu, and R. G. Bozomitu

Faculty of Electronics, Telecommunications and Information Technology, Gheorghe Asachi Technical University of Iași, Romania

P2.17 ID133 Analysis of Information Preservation in Image-Based Spectrogram Storage

A. Sârbu¹⁾, C. Neghină²⁾, M. Neghină²⁾

¹⁾ Nicolae Bălcescu Land Forces Academy, Sibiu, Romania

²⁾ Faculty of Engineering, Lucian Blaga University, Sibiu, Romania

P2.18 ID139 A CMOS Current Comparator with an Antiparallel Rectifier Pair as the Sole Decision Element for Current-Mode SAR ADCs

G. Bonteanu, A. Cracan, P. Bonteanu, and N. Cojan

Fundamentals of Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Gheorghe Asachi Technical University of Iași, Iași, Romania

P2.19 ID146 A Study on Ionization-Induced Negative Resistance of the Floating Current Sources in a Rail-to-Rail Class-AB CMOS Amplifier

N. Cojan, G. Bonteanu, A. Cracan and P. Bonteanu

Fundamentals of Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Gheorghe Asachi Technical University of Iași, Iași, Romania

P2.20 ID82 Design and Evaluation of a Level Shifter Circuit in 130 nm CMOS Technology

T. Grosu, A.-S. Gontean

Microelectronics, Politehnica University Timisoara, Timisoara/Romania

P2.21 ID87 A Digitally Programmable Hysteresis Rail-to-Rail CMOS Comparator

A. Moldovan, A. S. Gontean

Applied Electronics Department, Politehnica University, Timisoara, Romania

P2.22 ID115 Design and Simulation of a Rail-to-Rail Operational Amplifier with Folded Cascode in 130 nm CMOS

L.-M. Druțulesc, B. Marinca

Applied Electronics Department, Politehnica University, Timisoara, Romania

P2.23 ID147 BCD 130nm SRAM Design and Validation

A. R. Sicoe, A. Ș. Gontean

Applied Electronics Department, Politehnica University, Timisoara, Romania

P2.24 ID155 Influence of Photovoltaic Cell Geometry on MPPT Tracking Performance: A Co-Design Approach

D. Ionescu¹⁾, and Dan Butnicu²⁾

¹⁾ Department of Telecommunications and Information Technologies, Gh. Asachi Technical University of Iasi, Romania

²⁾ Department of Basics of Electronics, Gh. Asachi Technical University of Iasi, Romania

Friday, October 30

9:00 - 11:00

Plenary Oral Session 3

EEST | GMT +3h

Session Chair: Dorin PETREUȘ, Technical University of Cluj-Napoca, Romania

Session Co-Chair: Mihai NEGHINĂ, Lucian Blaga University of Sibiu, Romania

K3 Research and Engineering Education in the Age of AI: Opportunities, Boundaries, and Principles

Boris EVSTATIEV

Angel Kanchev University of Ruse

K4 ISOLDE: Building Blocks for High-Performance RISC-V System**Cătălin CIOBANU**

Associate Professor, Senior Researcher, Transilvania University of Braşov, Romania

03.1 ID81 RISC V Custom Function Unit for the Combinational Approximation for a Vector Norm

A. Andreas

Computer and Information Technology, Politehnica University, Timisoara, Romania

03.2 ID121 Controlled Shape Droplet Translation in 3D via Helmholtz–Anti-Helmholtz Coil SwitchingR. Alsangur, A. Turgut¹⁾, I. Ates²⁾, and L. Cetin³⁾

The Graduate School of Natural and Applied Sciences, Dokuz Eylül University, İzmir, Turkey

Department of Mechatronics Engineering, İzmir University of Economics, İzmir, Turkey

¹⁾ Department of Mechanical Engineering, Dokuz Eylül University, İzmir, Turkey²⁾ Mechatronics Program, Technical Sciences Vocational School, Uşak University, Uşak, Turkey³⁾ Department of Mechatronics Engineering, İzmir Kâtip Çelebi University, İzmir, Turkey**03.3 ID158 Reconstructing Missing Dam Displacement Data from Ambient Temperature Using Regression and Kalman Smoothing**

A. Flutur and S. Pop

Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

11:15 - 12:45 Poster Session 3 (Starts with a video pitching session in the plenary room, followed by discussion at the poster)**EEST | GMT +3h****Session Chair:** Mihai BRÂNZEI, National University of Science and Technology Politehnica Bucharest, Romania**Session Co-Chair:** Adriana BORODZHIEVA, Angel Kanchev University of Ruse, Bulgaria**P3.1 ID36 Automotive Head-Up Displays: Optical Principles, Enabling Technologies and Current Challenges**

M.A. Mocanu, O.M. Datcu, D.M. Moise, M. Nistor, and R. Ciobanu

Faculty of Mechanical Engineering and Mechatronics, National University of Science and Technology Politehnica Bucharest (UNSTPB), Bucharest, Romania

P3.2 ID39 Detection and Classification of Assembly Defects in SMT Assembly Processes Using Computer Vision Techniques

A. T. Hrabac, O. Vuap, G. I. Sacuiu, R. R. Ciobanu and C. Florea¹⁾

Mechatronics and Precision Mechanics Department, National University of Science and Technology Politehnica Bucharest, Bucharest, Romania

¹⁾Applied Electronics and Information Technology Department, National University of Science and Technology Politehnica Bucharest, Bucharest, Romania

P3.3 ID62 Dynamic Characterization of Electromechanical Disturbance Transmission in a Roll-to-Roll Digital Twin Prototype for Printed Electronics

R. Covaci, R. Gălătuș, L. Szolga

Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj Napoca, Cluj Napoca, Romania

P3.4 ID67 A Deterministic SCADE Architecture for Safe Automotive Over-the-Air Updates

M. Grosu¹⁾, R. Fizesan¹⁾, G. Flutur²⁾, and O. Pop¹⁾

¹⁾ Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Romania

²⁾ Faculty of Automation and Computer Science, Technical University of Cluj-Napoca, Romania

P3.5 ID69 Speeding Up Cryptography: A Survey on Algorithms Acceleration

Ș.-C. Tănăsescu¹⁾, C. B. Ciobanu^{1), 2)}

¹⁾Transilvania University of Brasov, Romania

²⁾National Institute of Research and Development in Microtechnologies, Bucharest, Romania

P3.6 ID73 Hardware-Software Co-Design and Virtual Validation Methods for Reducing Energy Consumption, Execution Time, and Certification Effort in Automotive Systems: A Comparative Study

G. Flutur¹⁾, A. I. Ilies²⁾, C. Corches¹⁾, and R. Jánó²⁾

¹⁾ Automation Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

²⁾ Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P3.7 ID104 Digital-Twin-Based Vital-Sign Monitoring

C. Onofrei, L. Viman, I. Baci, V. Bande and V. Veliciu

Applied Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P3.8 ID170 Geometric Parametric Optimization and Mixed-Mode Characterization of High-Speed Differential Vias

V. Cristescu, O. Axinte, M. Taut, M. Daraban, G. Chindris

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P3.9 ID153 Thermal Model Optimization of PCBAs for High-Current Testing of SMD Components

Z. Tafferner, A. Géczy

Department of Electronics Technology, Faculty of Electrical Engineering and Informatics, Budapest University of Technology and Economics, Budapest, Hungary

P3.10 ID175 TrustBridge-IoT: Cross-Layer Trust Management for Heterogeneous Automotive-IoT Infrastructures

A.A. Maftei, A. Lavric, A.I. Petrariu and V. Popa

Computers, Electronics and Automation Department, Stefan Cel Mare University of Suceava, Suceava, Romania

P3.11 ID176 Robust Waveforms for Automotive Communications: OTFS and OFDM in High-Mobility Scenarios

L. Ștefan and A. Lavric

Faculty of Electrical Engineering and Computer Science, Stefan Cel Mare University of Suceava, Suceava, Romania

P3.12 ID34 Comparative Analysis of Free and Commercial Simulation Tools for Power-Aware PCB Design in Engineering Education

E.-M. Grosu, A. Chioreanu, M.-C. Mareș, B. Mihăilescu, and P. Svasta

Centre for Technological Electronics and Interconnection Techniques, National University of Science and Technology POLITEHNICA Bucharest, Romania

P3.13 ID40 Alternative Learning Method for the Working Principle of Shift Register Circuits

N. C. Rohatinovici¹⁾, A. N. Dărau¹⁾, M. M. Nan¹⁾, M. Andraș¹⁾, and R. Rotar²⁾

¹⁾ Regina Maria Technological Highschool, Arad, Romania

²⁾ Department of Computer Science, Politehnica University, Timisoara, Romania

P3.14 ID46 Empirical Evaluation of LLMs for Automotive Requirements Engineering

P. L. Popescu-Cevei^{1,2)}, A. A. Rindasu^{1),3)}

1) AUMOVIO Romania, Timisoara, Romania

2) Universidad Americana de Europa, Mexico

3) Gheorghe Asachi Technical University of Iasi, Faculty of Electronics, Telecommunications and Information Technology, Iasi, Romania

P3.15 ID58 A Fredkin Only Construction of a Reversible Four-Input Multiplexer and Its Application to Three-Variable Boolean Synthesis

A. N. Borodzhieva

Department of Telecommunications, Angel Kanchev University of Ruse, Ruse, Bulgaria

P3.16 ID80 Exploring Reversible Digital Design via Toffoli Based Three Input Decoders and Function Synthesis

A. N. Borodzhieva

Department of Telecommunications, Angel Kanchev University of Ruse, Ruse, Bulgaria

P3.17 ID91 Autonomous Driving and Electromobility: An Interdisciplinary Online Course Developed within the TRIREME Project

B. Medgyes¹⁾, A. Gharaibeh¹⁾, S. Danieli²⁾, M. Di Frangia²⁾, E. Somano²⁾, M. Spanyol³⁾, and J. Stolfi³⁾

¹⁾ Department of Electronics Technology, Budapest University of Technology and Economics, Faculty of Electrical Engineering and Informatics, Budapest, Hungary

²⁾ Mylia – Adecco Formazione, Milan/Italy

³⁾ Department of Computer Science, VSB – Technical University of Ostrava, Faculty of Electrical Engineering and Computer Science, Ostrava, Czechia,

P3.18 ID109 Design and Implementation of a Web-Based Classroom Reservation System for Academic Environments

A.-I. Costea, R. János¹⁾

Faculty of Electronics, Telecommunications and Information Technology, Cluj-Napoca, Romania

¹⁾ Department of Applied Electronics, Faculty of Electronics, Telecommunications and Information Technology, Cluj-Napoca, Romania

P3.19 ID128 CardioSight: A Deep Learning Platform for Cardiac MRI

C. B. Ciobanu^{1),2)} and M.C. Saulea²⁾

¹⁾ National Institute of Research and Development on Microelectronics, Romania

²⁾ Transilvania University of Braşov, Integrated Systems Master's Degree, Romania

P3.20 ID148 Raising Awareness by Digital Education in Cybersecurity for Electronic Designers

L. Scripcariu, F. Mocanu, A. M. Mazilu, C. V. Tanasă, I. Bogdan, R. G. Bozomitu

Gheorghe Asachi Technical University of Iaşi, Romania

P3.21 ID162 Design and Educational Simulation of Reversible Half Subtractor and Full Subtractor Using TSG Gates in Logisim

A. N. Borodzhieva

Department of Telecommunications, Angel Kanchev University of Ruse, Ruse, Bulgaria

P3.22 Beyond Headline Accuracy: Quantitative Analysis of Machine-Learning Fault Diagnosis Evidence for Reliable Electronics

Ioana R. Goldbach¹⁾, Felix G. Hamza-Lup²⁾, Nicoleta Angelescu³⁾

1) Department of Management, Valahia University of Târgoviște, Târgoviște, Romania

2) Department of Computer Science Georgia Southern University, Georgia, USA

3) Department of Electronics, Telecommunications and Energy Engineering, Valahia University of Târgoviște, Târgoviște, Romania

P3.23 A Comparative Latency Model for 2G/3G/4G/5G Mobile Networks Using Realistic Physical Parameters

Felicia Georgiana Chita, Nicoleta Angelescu, Gabriel Predusca, Ion Caciula, Liana Denisa Circumarescu, Dan Constantin Puchianu

Department of Electronics, Telecommunications and Energy Engineering, Valahia University of Targoviste, Targoviste, Romania

13:45 - 15:45

Plenary Oral Session 4 - Online

EEST | GMT +3h

Session Chair: Alexandra FODOR, Technical University of Cluj-Napoca, Romania

Session Co-Chair: Cristina MARGHESCU, POLITEHNICA Bucharest, Romania

K5 News about RFID Antennas

Mihai GABOR

Technical University of Cluj-Napoca, Romania

O4.1 ID98 Optical Coherence Tomography Between X-ray Imaging and Scanning Electron Microscopy for Multiscale Material Characterization

R.-A. Erdelyi, and V.-F. Duma

3OM Research Group, Department of Measurements and Electro-Optics, Polytechnic University of Timișoara, Timișoara, Romania

O4.2 ID134 Methodology for Quantitative Evaluation of Void-Like Defects in BGA Solder Joints Using X-Ray Image Processing

R. C. Ionel, L. Mățiu-Iovan, M. A. Mercioni*, C. M. Drăgan, L. I. Cădariu-Brăiloiu, B. L. Rădulescu

Politehnica University Timisoara, Timisoara, Romania

Quality Lab Technologies Automotive AUMOVIO Technologies Romania

O4.3 ID171 Differential Impedance Optimization of Wire-Bond Package Interconnects Through Capacitive Trace Compensation

O. Axinte, V. Cristescu, M. Taut, G. Chindris, M. Daraban

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

15:45 - 17:10

Poster Session 4 (Starts with a video pitching session in the plenary room, followed by discussion at the poster)

EEST | GMT +3h

Session Chair: Cristian Marcel FARCAȘ, Technical University of Cluj-Napoca, Romania, Bulgaria

Session Co-Chair: Bogdan MIHĂILESCU, POLITEHNICA Bucharest, Romania

P4.1 ID56 Thermal Characterization of Electronic Systems: A Review of Standards, Methods, and Current Trends

V. Cristescu¹, M. Oltean¹, A. Fodor², I. Ciocan², C. Farcas²)

¹) Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania,

²) Applied Electronics Department, Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.2 ID102 Novel Aspects of Magnetic Component Design in LLC Converters

L. Manciu, D. Petreus

Applied Electronics, Technical University of Cluj-Napoca, Cluj, Romania

P4.3 ID123 Development of an Intelligent Sensorless Control Platform for BLDC/PMSM Motors with Model-in-the-Loop Validation

N. E. Bondric, M.A. Taut, G.Chindris, A. Taut

Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.4 ID138 Experimental Benchmarking of Advanced and Conventional Silicon Power MOSFETs

D. Samoila¹, E. Vesa², V. Petrascu³, A. Tulbure⁴)

¹) 1 December 1918 University of Alba Iulia, Romania

²) National University of Science and Technology POLITEHNICA Bucharest, Romania

³) National University of Science and Technology POLITEHNICA Bucharest, Romania

⁴) Department of Informatics, Mathe & Electronics, 1 Decembrie 1918 University of Alba Iulia, Romania

P4.5 ID149 Thermal Design Optimization of Automotive Electronic Modules Through PCB and Hybrid Enclosure Architectures

A. Popovici, C. Fărcaș, I. Ciocan, A. Fodor

Department of Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.6 ID156 Nyquist Based Analogy of Reliability Prediction for PoL Input Capacitors with Hands-on Experimental Validation

D. Butnicu, D. Ionescu

Faculty of Electronics, Telecommunications and Information Technology, Gh.Asachi Technical University of Iasi, Romania

P4.7 ID157 Analysis of Housing Options and Passive Cooling Solutions for Quad Flat No-Lead Packages

M.C. Oltean, G. Nastuta, A. Fodor¹⁾, C. Farcas¹⁾, I. Ciocan¹⁾, C. M. Dragan²⁾, C. Popescu²⁾, C. Aluca²⁾, L. Bodin²⁾

Faculty of Electronics, Telecommunications and Information Technology, Technical University of Cluj-Napoca, Cluj-Napoca, Romania,

¹⁾ Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania,

²⁾ AUMOVIO Technologies Romania SRL

P4.8 ID159 Co-Design of Photovoltaic Modules and MPPT Boost Converters: Investigating the Influence of Photovoltaic Characteristics on Converter Design

R.-N. Susanu²⁾, S. Kadirova¹⁾, B. Evstatiev¹⁾, D. Ionescu²⁾

¹⁾ Department of Automatics & Electronics, Angel Kanchev University of Ruse, Bulgaria

²⁾ Department of Telecommunications and Information Technologies, Gheorghe Asachi Technical University of Iasi, Romania

P4.9 ID55 Design of a Smart Monitoring System for Renewable Energy Communities Using IoT Technologies

F.-A. Tornea¹⁾, S. Andries¹⁾, M. Hnatiuc¹⁾, D. Alperti²⁾

¹⁾ Department Electronic and Telecommunication, Constanta Maritime University, Constanta, Romania

²⁾ Doctoral School of ETIT, National University of Science and Technology POLITEHNICA Bucharest, Bucharest, Romania

P4.10 ID86 PSIM Model of PEM Fuel Cells with Boost Converter within a DC Microgrid

L. Moga, D. Petreuş, and D. Fodorean¹⁾

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

¹⁾ Electrical Machines and Drives, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.11 ID95 Comparative State of Charge Estimation for NCR18650B Lithium-Ion Cells Using Coulomb Counting and Regression Trees

M. Olteanu and D. Petreuş

Applied Electronics Department, Technical University of Cluj-Napoca, Romania

P4.12 ID97 Implementation of a Modular, Parameter-Driven Mathematical Simulation Model for PEM Fuel Cells

D. A. Bulugheană, and D. M. Petreuş

Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.13 ID105 WebGIS for Climate Resilience and Nature-Based Solutions

T. Pintilie, C. Dobre, R. Streche, A. Dănilă, A. Borbak, G. Suci

R&D Department, BEIA Consult International, Bucharest, Romania

P4.14 ID113 An Autonomous Dust Removal System for Enhanced Efficiency of Photovoltaic Modules

A.-M. Rad¹⁾, D. Csipkes²⁾, G. Csipkes²⁾, and E.-M. Stetco¹⁾

¹⁾ Applied Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

²⁾ Bases Of Electronics, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.15 ID150 Small wind turbine architecture with stepper motor generator

R. Rizea, S. C. Olteanu, C. G. Lupu

National University of Science and Technology Politehnica Bucharest, Bucharest, Romania

P4.16 ID154 Influence of PV Plant Configuration on the Energy Balance of Residential Buildings

E. Vesa¹⁾, A. Tulbure²⁾, O. C. Novac³⁾, M. Damian ¹⁾, P. Barbat¹⁾

¹⁾ PhD Student, National University of Science and Technology POLITEHNICA Bucharest, Romania

²⁾ Department of Informatics, Mathematics and Electronics, 1 Decembrie 1918 University of Alba Iulia, Romania

³⁾ Department of Computers and Information Technology, Faculty of Electrical Engineering and Information Technology, University of Oradea, Romania

P4.17 ID165 Comparative Characterization of Round and Rectangular Dye-Sensitized Solar Cells for Indoor Energy Harvesting

A. C. Popescu^{1),2)}, M. C. Mareş^{1),2)}, D. Ursu³⁾, M. Miclău³⁾, R. C. Negroiu^{1),2)}, C.I. Marghescu¹⁾, P. M. Svasta¹⁾

¹⁾ Centre for Technological Electronics and Interconnection Techniques

National University of Science and Technology POLITEHNICA Bucharest, Romania

²⁾ IEEE Nanotechnology Council Student Branch Chapter of POLITEHNICA Bucharest, NANO42, SBC63061A, National University of Science and Technology POLITEHNICA Bucharest, Romania

³⁾ Department of Condensed Matter, National Institute of Research and Development for Electrochemistry and Condensed Matter, Timisoara, Romania

P4.18 ID37 Experimental Platform for Measuring Pixel Transition Dynamics in Automotive Displays

D. M. Moise, O. M. D. Datcu, B. E. Preoteasa, M. Zanfir and I. Grămescu

Mechatronics and Precision Mechanics Department, National University of Science and Technology POLITEHNICA Bucharest, Romania

P4.19 ID126 Reliability Impact of Flat Wire Inductor Technology in PoL Converters: A MIL HDBK 217F and IR-Thermography Investigation

D. Butnicu¹⁾, R. Tristu²⁾

¹⁾ Electronics Faculty, Technical University of Iasi, Iasi, Romania

²⁾ Electronics Department, Technical College Remus Radulet, Brasov, Romania

P4.20 ID127 The Link Between PoL Converter Reliability and CO2 Footprint Reduction: Focus on Output Capacitors

R. Tristu¹⁾, D. Butnicu²⁾

¹⁾ Electronics Department Technical College Remus Radulet, Brasov, Romania

²⁾ Electronics Faculty, Ghe. Asachi Technical University of Iasi, Iasi, Romania

P4.21 ID110 A Secure, Power-Optimized Autonomous Mobile Robot with Real-Time Telemetry and Maze-Solving Capabilities

D. Pescariu, V. Tomoiagă, A. Zăuleț, and A. Grama

Applied Electronics Department, Technical University of Cluj-Napoca, Cluj-Napoca, Romania

P4.22 ID112 Wideband UHF Spectrum Mapping System using USRP E310

C.C. Nechifor, Cs.Z. Kertész

Electronics and Computers Department, Transilvania University of Braşov, Romania

SIITME 2026 Committees

General Chair:

Paul SVASTA, POLITEHNICA of Bucharest, Romania
Association for Promoting Electronics Technology

General Co-Chair:

Ovidiu Aurel POP, Technical University of Cluj-Napoca, Romania

Conference Chair:

Nicoleta ANGELESCU, Valahia University of Târgoviște, Romania

Conference Co-Chair:

Henri-George COANDĂ Valahia University of Târgoviște, Romania

Technical Program Chair:

Norocel CODREANU, POLITEHNICA Bucharest, Romania

Technical Program Co-Chairs:

Cristina MARGHESCU, POLITEHNICA Bucharest, Romania
Detlef BONFERT, Fraunhofer EMFT, München, Germany

Awards Committee Chairs:

Heinz WOHLRABE, Dresden University of Technology, Dresden, Germany
Cristina MARGHESCU, POLITEHNICA Bucharest, Romania

Scientific Committee Chair:

Ciprian IONESCU, POLITEHNICA Bucharest, Romania

Scientific Co-Chairs:

Heinz WOHLRABE, Dresden University of Technology, Germany

Exposition Committee Chair:

Rajmond JÁNÓ, Technical University of Cluj Napoca, Romania

Exposition Committee Co-Chairs:

Adelina-Ioana ILIEȘ, Technical University of Cluj Napoca, Romania

Publication Chair:

Alexandra FODOR, Technical University of Cluj- Napoca, Romania

Publication Co-Chair:

Bogdan MIHĂILESCU, POLITEHNICA of Bucharest, Romania

Media Publisher Committee Chair:

Cătălina NEGHINĂ, Lucian Blaga University of Sibiu, Romania

Social Media Committee Chair:

Monica CIOLACU, University of Bundeswehr Munich, Germany

Local Organising Committee***Valahia University of Târgoviște, Romania*****Chair:**

Gabriel CROITORU

Co-Chairs:

Cristina Mihaela NICOLESCU

Iulian Nicolae UDROIU

Aurora Aurelia DIACONESCU

Members:

Dan Constantin PUCHIANU

Catalin DRAGOI

Ion CACIULA

Liviu OLTEANU

Andrei MILITARU

Emanuel BUICĂ

Iuliana Roxana ONOFREI

Technical Secretariat**Chair:**

Delia LEPĂDATU, Politehnica of Bucharest, Romania

Members:

Cristina Mihaela BRAGADIRU, Politehnica Bucharest, Romania,

Association for Promoting Electronics Technology, Romania

Mariana PĂTULEANU, Politehnica Bucharest, Romania,

Association for Promoting Electronics Technology, Romania

Andrei Cristian POPESCU, Politehnica Bucharest, Romania

Florentina STĂLINESCU, Politehnica Bucharest, Romania

***For detailed committee please visit www.siitme.ro**

SIITME 2026 Reviewers

Chair:

Gabriel CHINDRIȘ, Technical University of Cluj-Napoca, Romania

Members:

Dorel AIORDĂCHIOAIE, Dunărea de Jos University of Galați, Romania
 Adrian BOTUȘESCU, AUMOVIO, Romania
 Radu Gabriel BOZOMITU, Gheorghe Asachi Technical University of Iași, Romania
 Gabriel CHINDRIȘ, Technical University of Cluj-Napoca, Romania
 Cătălin CIOBANU, Transilvania University of Brașov, Romania
 Mihaela CÎRLUGEA, Technical University of Cluj-Napoca, Romania
 Eugen COCA, Ștefan cel Mare University of Suceava, Romania
 Rodica-Claudia CONSTANTINESCU, POLITEHNICA Bucharest, Romania
 Cosmina CORCHEȘ, Technical University of Cluj-Napoca, Romania
 Mihai DĂRĂBAN, Technical University of Cluj-Napoca, Romania
 Andrei DRUMEA, POLITEHNICA Bucharest, Romania
 Alexandra FODOR, Technical University of Cluj-Napoca, Romania
 Aurel-Ștefan GONTEAN, POLITEHNICA University of Timișoara, Romania
 Alin GRAMA, Technical University of Cluj-Napoca, Romania
 Adelina-Ioana ILIEȘ, Technical University of Cluj-Napoca, Romania
 Zsolt ILLYEFALVI-VITÉZ, Budapest University of Technology and Economics, Hungary
 Rajmond JÁNÓ, Technical University of Cluj-Napoca, Romania
 Olivér KRAMMER, Budapest University of Technology and Economics, Hungary
 Alina Elena MARCU, POLITEHNICA Bucharest, Romania
 Cristina MARGHESCU, POLITEHNICA Bucharest, Romania
 Bogdan MIHĂILESCU, POLITEHNICA Bucharest, Romania
 Mădălin MOISE, POLITEHNICA Bucharest, Romania
 Rodica Cristina NEGROIU, POLITEHNICA Bucharest, Romania
 Viorel NICOLAU, Dunărea de Jos University of Galați, Romania
 Ciprian ORHEI, POLITEHNICA University of Timișoara, Romania
 Mihaela PANTAZICĂ, POLITEHNICA Bucharest, Romania
 Dorin PETREUȘ, Technical University of Cluj-Napoca, Romania
 Ovidiu Aurel POP, Technical University of Cluj-Napoca, Romania
 Vijay N. SONTAKKE, Intel Corporation
 Paul SVASTA, POLITEHNICA Bucharest, Romania
 Adrian TĂUT, Technical University of Cluj-Napoca, Romania
 Alexandru VASILE, POLITEHNICA Bucharest, Romania
 Cristian VRĂNCILĂ, AUMOVIO Technologies Romania
 Heinz WOHLRABE, Dresden University of Technology, Germany

SIITME 2026 Posters Assessor Committee

Nicoleta ANGELESCU, Valahia University of Târgoviște, Romania
 Ioan-Adrian BOJITA, Technical University of Cluj-Napoca, Romania
 Attila BONYAR, Budapest University of Technology and Economics, Hungary
 Gabriel BONTEANU, Gheorghe Asachi Technical University of Iași, Romania
 Adriana BORODZHEVA, University of Ruse Angel Kanchev, Bulgaria
 Radu Gabriel BOZOMITU, Gheorghe Asachi Technical University of Iași, Romania
 Mihai BRANZEI, POLITEHNICA Bucharest, Romania
 Gabriel CHINDRIS, Technical University of Cluj-Napoca, Romania
 Catalin CIOBANU, Politehnica University Timisoara, Romania
 Arcadie CRACAN, Gheorghe Asachi Technical University of Iasi, Romania
 Boris EVSTATIEV, University of Ruse Angel Kanchev, Bulgaria
 Cristian Marcel FARCAS, Technical University of Cluj-Napoca, Romania
 Alexandra FODOR, Technical University of Cluj-Napoca, Romania
 Alin GRAMA, Technical University of Cluj-Napoca, Romania
 Daniela IONESCU, Gheorghe Asachi Technical University of Iasi, Romania
 Rajmond JÁNÓ, Technical University of Cluj-Napoca, Romania
 Csaba Zoltán KERTÉSZ, Transilvania University of Brasov, Romania
 Cristina MARGHESCU, POLITEHNICA Bucharest, Romania
 Bálint MEDGYES, Budapest University of Technology and Economics, Hungary
 Bogdan MIHAILESCU, POLITEHNICA Bucharest, Romania
 Madalin MOISE, POLITEHNICA Bucharest, Romania
 Mihai NEGHINA, Lucian Blaga University of Sibiu, Romania
 Rodica NEGROIU, POLITEHNICA Bucharest, Romania
 Cristina Mihaela NICOLESCU, Valahia University of Targoviste, Romania
 Liviu OLTEANU, Valahia University of Targoviste - ICSTM, Romania
 Mihaela PANTAZICA, POLITEHNICA Bucharest, Romania
 Toma PATARAU, Technical University of Cluj-Napoca, Romania
 Dorin PETREUS, Technical University of Cluj-Napoca, Romania
 Radu PREDA, NXP Electronics, Romania
 Ionut Razvan RADULESCU, INCDTP, Bucuresti
 Alexandru VASILE, POLITEHNICA Bucharest, Romania
 Daniel Ciprian VASILE, POLITEHNICA Bucharest, Romania
 Emilia VISILEANU, INCDTP - Bucharest, Romania

Industry



Precision. Insight. Performance.

Advanced test & measurement solutions for high-speed electronics

Accurate measurements are essential for faster development and confident design decisions. **ARC Braşov** provides advanced test & measurement solutions, including the Teledyne LeCroy WaveMaster 8000HD, designed for demanding high-speed electronic applications.

- ☑ Up to 65 GHz bandwidth for high-speed signal analysis
- ☑ 12-bit vertical resolution for exceptional waveform detail
- ☑ Up to 320 GS/s sampling rate for advanced signal acquisition
- ☑ SDA Expert Serial Data Analysis with Eye Diagram, Jitter & Noise Analysis
- ☑ Up to 4 inputs at 33 GHz for multi-channel measurements

Advanced analysis for high-speed signals

The **WaveMaster 8000HD** delivers the bandwidth, resolution and analysis capabilities required for the development, debugging and validation of next-generation electronic systems. Its advanced Serial Data Analysis tools provide detailed insight into signal integrity and high-speed communication interfaces. From design verification and debugging to compliance testing and validation, ARC Braşov delivers the measurement performance engineers need for demanding electronic applications.

Discover advanced test & measurement solutions - ARC Braşov

arc@arc.ro Tel: 0268-472 577, www.arc.ro , blog.arc.ro, comunitate.arc.ro



ARC Braşov



In Romania, **AUMOVIO** has a strong national presence, with operations in Braşov, Iaşi, Sibiu, and Timișoara. The company runs four research and development centers (R&D) and two production facilities, located in Sibiu and Timișoara. The Romanian team includes approximately 12,000 employees, with more than half being engineers and IT specialists working in R&D.

All the company's global business areas are also represented in Romania, ensuring a complete and well-established presence on the local market.



The **Autonomous and Commercial Mobility (ACM)** business area offers a comprehensive range of products for automated and autonomous driving, holding a leading position in the global market for commercial vehicles and key autonomous driving components and systems (e.g.: sensors, radars, etc.). With its “as a service” approach, the business area is also tapping into new business models.

The Architecture and Network Solutions

(ANS) business area is geared to the key requirements of the software-defined vehicle, with a product portfolio encompassing high-performance computers, telematics, drive systems, sensors and actuators. Today, ANS already occupies a leading market position with around 90 percent of its core product portfolio.



With more than 100 years of experience in vehicle safety, the **Safety and Motion (SAM)** business area is one of the global market leaders in brake systems, integrated safety systems and sensor systems. The business area is a pioneer in developing dry brake systems and was one of the first suppliers to receive a high-volume order for a semi-dry



brake system. AUMOVIO sees tremendous potential for the future in these brake systems due to their improved product characteristics.

In the **User Experience (UX)** business area, AUMOVIO is a leading provider of display solutions and head-up displays. UX has a broad and diversified portfolio ranging from modern high-tech displays

to competitive products for the high-volume market. UX expects the value of components installed per vehicle to increase in the future, driven by larger displays and new products such as scenic view head-up displays that extend across the full length of the dashboard. Furthermore, UX intends to consolidate its competitive strength by leveraging economies of scale in production in its megafactories.

AUMOVIO Technologies Romania SRL

str. Siemens 1, 300701 Timisoara |
Romania

Phone: 0256251100

Web: www.aumovio.com





Bosch Engineering Center Cluj plays an essential role in the great transformation of the mobility sector ever since its foundation in 2013. With vast expertise in software, hardware & mechanical and reliability engineering, but also in sales planning, the Center contributes to the development of excellent products, services and innovative AI-based solutions for **automated driving, connected & electric mobility**. Thanks to the close collaboration with other Bosch engineering centers and with Bosch Cluj Plant, and to its state-of-the-art offices and laboratories from Cluj-Napoca, Jucu and Bucharest, the Center offers unique solutions to its clients from around the world.

At Bosch Engineering Center we value and invest in educational programs, and in partnership with the Technical University of Cluj-Napoca and Babeş-Bolyai University we offer **3 Master's Programs** and **4 courses** for university students.



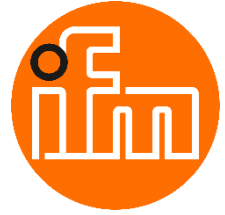
Work #LikeABosch
@Engineering Center Cluj

[bosch.ro/cariere](https://www.bosch.ro/cariere)



Read more: <https://www.bosch.ro/en/our-company/bosch-in-romania/bosch-engineering-center/>

ifm – Technology, Innovation and Quality in Automation



The German group **ifm**, a global leader in the development of sensors, automation systems and digital solutions, is present in Romania (Sibiu) through three divisions:

- ◆ **ifm efector** – production of position sensors
- ◆ **ifm prover** – production of process sensors
- ◆ **ifm electronic** – sales division

Founded in 1969, **ifm** combines the strength of an international group with the flexibility of a medium-sized company, with 9,005 employees in 150 countries..

What defines us?

- ✓ Open and people-oriented management
- ✓ Fast and efficient decision-making
- ✓ Investments in employee development
- ✓ Modern work environments
- ✓ Promoting a healthy lifestyle

Our mission is to become a benchmark in the Western Industrial Zone of Sibiu, being not just a supplier, but a trusted partner for customers and an exceptional employer.

◆ ifm values:

- ✓ **Innovation** – Cutting-edge technology for automation
- ✓ **German quality** – Reliable, rigorously tested products
- ✓ **Customer orientation** – Personalized consulting
- ✓ **Sustainability** – Energy-efficient solutions

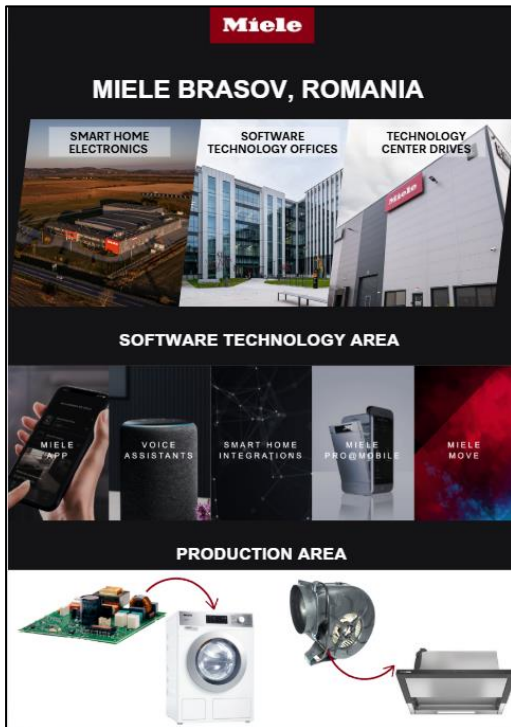
ifm solutions for industry:

- ✚ **Industrial sensors** – proximity, position, pressure, temperature detection
- ✚ **Diagnostic systems** – monitoring and predictive maintenance
- ✚ **Controllers & IO-Link** – efficient communication between devices
- ✚ **Software Industrie 4.0** – real-time data analysis

Industries served:

- 🚗 **Automotive** – Automation and quality control
- 🍷 **Food industry** – Production process safety
- 📦 **Logistics & Transport** – Smart Monitoring
- ⚡ **Energy & Environment** – Efficiency and Sustainability

💡 At **ifm**, we continuously innovate to contribute to a more efficient and sustainable future!



Miele - Premium brand for more than 125 years

As the world's leading manufacturer of premium domestic appliances, we create delightful experiences – not only regarding the quality of our products, but also in terms of performance, design, technology, and sustainability.

Miele is an independent family-owned company since its establishment in 1899 and is equally committed to its owners, employees, customers, suppliers, the environment and society.

Miele stands for long-term thinking and planning, continuity of values and goals, good relationships with customers and suppliers, as well as an employee-oriented corporate and leadership culture. Miele offers products to its customers that set the standards for durability, performance, ease of use, energy efficiency, design and service.

Since 2009, **Miele Tehnica in Braşov, Romania**, has been part of this legacy , experiencing sustainable growth. Today Miele Brasov represents a reliable partner for the entire **Miele Group**.

As part of the Smart Home Electronics division, we have developed business areas in Braşov:

- since 2009 - Operations Electronic Production area
- since 2015 - Software Technology Development Center area
- since 2021 - Global IT Services area
- since August 2024 - Operations Technology Center Drives area

Within the Software Technology Area, we have been developing new competencies since 2015, growing our business with the Development Center Area (Electronic Product Development and Digital Product Development) and the Global IT (IT Service Desk, IT Infrastructure, and IT Engineering).

We create and develop innovative digital solutions that inspire customers.

Our skilled colleagues design advanced solutions that enhance the Miele experience for users around the globe.

At our state-of-the-art Production Plant in Feldioara we assemble electronic power boards and mechanical components that serve as the core of the control systems for Miele appliances.

Within the Technology Center Drives in Braşov, we perform the pre-assembly and final assembly of the various systems that will later be installed in Miele appliances.

Our vision in Brasov "We at Miele develop ourselves to have a premium experience" is derived from Miele's philosophy "Immer Besser" / „Always Better".

Keeping this vision in mind , we ensure that we deliver a Premium Employee and Customer Experience.

Link to Carrer Page Miele - [Miele Carieră în România: Explorează-ți viitorul](#)



As a world leader in secure connectivity solutions for embedded applications, **NXP Semiconductors** is pushing boundaries in the automotive, industrial & internet of things (IoT), mobile, and communication infrastructure markets while delivering solutions that advance a more sustainable future.



The company has experienced substantial growth over the past few years. In May 2023, it opened its second research and development (R&D) center in Sibiu and continues to actively recruit, with open positions available across all key development areas.

NXP Romania contributes to the development of solutions for automotive, consumer and industrial IoT markets by developing software platforms that integrate NXP components and software from partners. In addition to software development, NXP also invests in research as part of intellectual property creation programs.

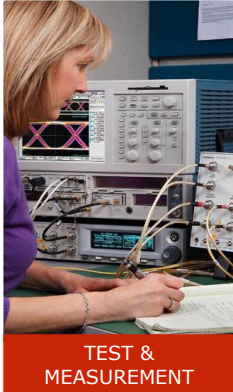


The R&D centers of excellence have more than 20 years of experience in designing, developing and innovating software products. The center of excellence in Bucharest focuses on two areas in continuous transformation: automotive and IoT. As automotive architectures are evolving, the teams are specialized in developing integrated software products that enhance customer experience by providing reference hardware and software platforms that are easy to use and configure. NXP also has dedicated teams that focus on IT service management and chip sales and order management operations.



Each year, **NXP Romania** hosts interns who learn the specifics of software development in Automotive, Edge Computing and IoT. We are proud that our interns extend their experience with practical contributions in real-life projects. Search for latest internship openings on <https://shorturl.at/hkluP>.

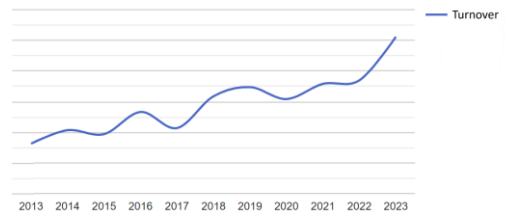
One COMPANY, THREE BUSINESS SEGMENTS



Delivering Excellence
in Technology and Business
since more than 25 years



Exceeding a turnover of
10 million EUR



ROMTEK's OFFER includes:

-  Consulting services;
-  Application engineering support;
-  System design;
-  Project management;
-  Equipment supply;
-  Equipment / System Installation, Commissioning and Certification;
-  Training;
-  Service & maintenance, Calibration and Metrological verification.

 Whenever required, **RomTek** can also offer **financing solutions** through 3rd party specialized companies/institutions

Equipment / Solutions for TEST & MEASUREMENT:

Academic-Level Educational Training Platforms • **General-Purpose T&M Instrumentation** (Oscilloscopes, Signal Generators, Spectrum and Signal Analyzers, Digital Multimeters, Data Acquisition Systems etc) • **Low-level Instruments / Sensitive and Specialty Instruments** (SMUs, Picoammeters, Ultra-Sensitive Current Sources, Ultra-Low Resistance Meters, Nanovoltmeters, Electrometers) • **Semiconductor Parameter Analyzers** (for component and wafer testing) covering I-V, C-V and ultra-fast pulsed I-V tests • **Probing Stations and Probe Cards** (for Advanced Semiconductor Wafer Thermal Testing) • **Sources and Supplies** (AC+DC Power Supplies, AC+DC Electronic Loads, Bidirectional Power Supplies, Grid Simulators, Battery Testers) • **EMC Compliance and RF Solutions** (CE, CI, RE, RI test systems, ESD, H&F, Dips, Interrupts & Variations, Transient Generators (Burst/Surge), Magnetic Fields), RF Amplifiers (Solid State, Pulsed TWT, Milimeter TWT), RF Immunity Test Systems • **EMC Infrastructure** (EMC & Reverberation Anechoic Chambers, EMC Tents, EMC Antennas, Turn-tables, Filters, Positioners etc) • **Acoustic T&M Instrumentation and Infrastructure** (test microphones & analyzers, acoustic chambers).



Equipment / Solutions for TELECOM:

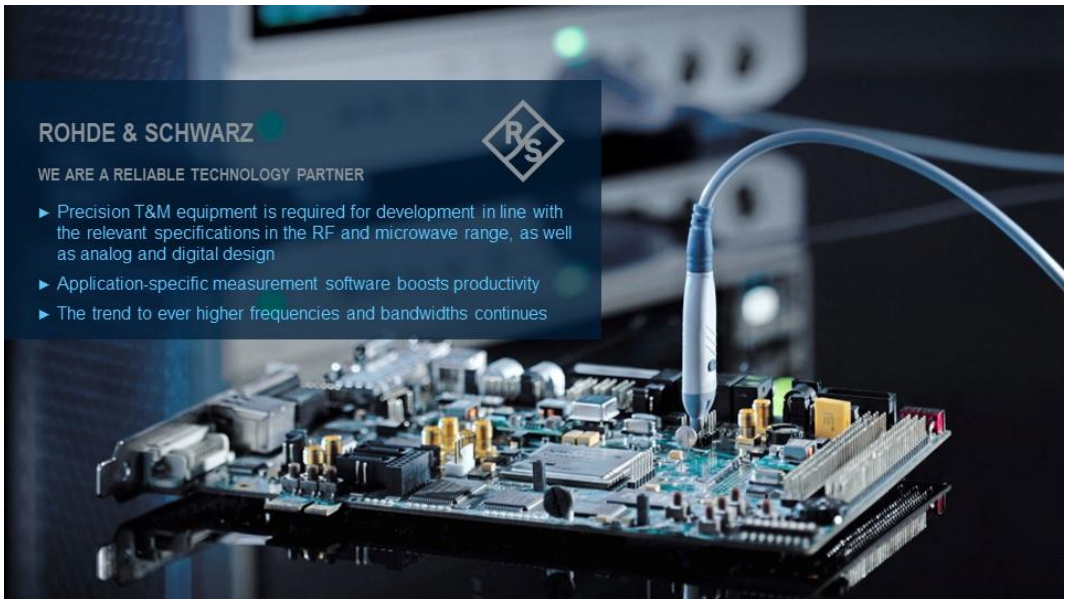
DVB and IP Digital Head-ends • **DVB Turn-key Platforms** (CATV, DTH, DTT) • **OTT** • **Video Processing** (encoding, transcoding, conversion etc.) • **Video Contribution & Distribution** (via Satellite, Fiber, IP & Cloud) • **Infrastructure for Remote Video Production** • **Network Management and Monitoring** • **Middleware and Conditional Access** • **GPON / FTTH infrastructure** • **CPEs** (ONTs, STBs etc.)



Equipment / Solutions for AUDIO|VIDEO|TV|FILM:

TV and Radio Studios • **Virtual & Augmented Reality Systems** • **OB and DSNG Vans** • **Airborne Broadcast Systems** (installed on drones or helicopters) • **Fly-Away Systems** • **Newsroom Computer Systems** • **On/Off-Air Graphics Systems** • **Master Control and Playout facilities** • **A|V Post-Production Systems** • **Restoration and Digital Format Conversion** • **Digital Cinematography**





Rohde & Schwarz is a global technology group striving for a safer and connected world. With its Test & Measurement, Technology Systems and Networks & Cybersecurity Divisions, the company creates tomorrow's innovations today. The company's leading-edge products and solutions empower industrial, regulatory and military customers to attain technological and digital sovereignty.

Innovation has been part of Rohde & Schwarz since the very beginning. The company founders Dr. Lothar Rohde und Dr. Hermann Schwarz were technological pioneers. With their hands-on entrepreneurial spirit, the two college friends entered the unexplored field of RF engineering. Ninety years later, the company is still pushing technological boundaries – as a successful shaper of cutting-edge technologies such as artificial intelligence (AI), 6G, cloud and quantum technologies.

The privately owned company is known for stability and resilience. Independence is at the core of its entrepreneurial identity. The company finances its growth with its own resources. Because the company does not have to think in terms of quarterly results, it can plan sustainably for the long term. The high added value of Rohde & Schwarz makes the company a reliable, trustworthy and relevant partner for its customers.

TEST & MEASUREMENT

Wireless | Industry,
Components & Research |
Aerospace & Defense
Testing | Automotive

TECHNOLOGY SYSTEMS

Secure Communications |
Critical Infrastructure &
Networks | Government |
IP Network Analytics |
Broadcast, Amplifiers &
Media

NETWORKS & CYBERSECURITY

Endpoint Security | Secure
Networks | Certified &
High-Grade Crypto
Solutions



Syntegra Security SRL is a private commercial company, established in 2008, specialized in the design, installation and maintenance of electrical installations and physical security systems (intrusion detection and alarm systems, access control systems, closed circuit television, fire detection and alarm systems).

CERTIFICATION

✚ SC Syntegra Security SRL is authorized by the General Inspectorate of the Romanian Police with license 2725/T from 4.04.2013 in order to design, install and maintain burglar alarm systems;

✚ SC Syntegra Security SRL holds the following authorizations from the General Inspectorate for Emergency Situations:

- Authorization Series A no. 2404 of 03.03.2023 for the design of signalling, alarm and fire warning systems and installations;
- Authorization Series A no. 2405 of 03.03.2023 for installation and maintenance of signaling, alarming and alerting systems and installations in case of fire;

✚ SC Syntegra Security SRL holds the following certificates from the National Energy Regulatory Authority:

- Certificate no. 21486 of 22.02.2024 of type Be for "execution of external/internal electrical installations for civil and industrial premises/construction, aerial and underground connections, at the nominal voltage of 0.4 kV";

Certificate no. 21487 of 22.02.2024 of type C1A for "design of electrical lines, overhead or underground, with a nominal voltage of 0.4 kV ÷ 20 kV, transformer stations with a nominal voltage higher than 20 kV, medium voltage stations, such as and the medium-voltage electrical part of high-voltage substations".



www.syntegra.ro

office@syntegra.ro

Research

ASSOCIATION FOR PROMOTING ELECTRONICS TECHNOLOGY (ASOCIAȚIA PENTRU PROMOVAREA TEHNOLOGIEI ELECTRONICE) IMAPS ROMANIA

APTE



A globally-competitive workforce with theoretical, as well as applied engineering/hands-on, education must be trained. In addition to the areas of science, engineering, microelectronics, and packaging, this training must encompass the broader areas of business, economics, ethics, foreign culture, and languages.



The Association for Promoting Electronics Technology (APTE, see <https://apte.org.ro/>) is IMAPS Romania. APTE was founded in 2003, by the Center for Technological Electronics and Interconnection Techniques (UPB-CETTI) together with highly respected members of the electronics industry, in order to support the electronics packaging education and engineering, in a climate of trust, ethics, and social responsibility.

APTE/IMAPS Romania is the management entity of the ELINCLUS Cluster (see <http://elinclus.ro/>), which has currently 94 members. ELINCLUS was established starting from the economic relationship existing between UPB-CETTI (which developed a Technological and Business Incubator, entity accredited by the National Innovation and Technology Transfer Network – ReNITT) and companies from Bucharest and Ilfov county. This structure has offered to ELINCLUS the status of a regional cluster in the field of electronics.

APTE offers annually a comprehensive set of short courses and training classes in the area of electronics packaging, IPC standards certification, management, and industrial development, in order to serve the needs of the electronics industry. APTE organises annually The International Symposium for Design and Technology in Electronics Packaging (SIITME, see <http://siitme.ro/>) and the Interconnection Techniques in Electronics (TIE, see www.tie.ro/) Professional Student Design Contest.

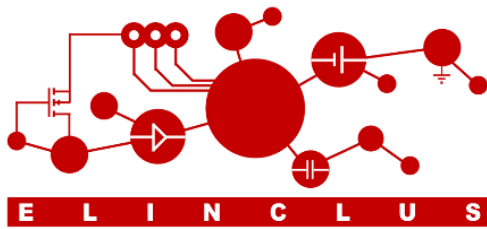


Contact:

Phone: +40214103108

E-mail: apte@apte.org.ro





ELINCLUS Electronic INnovation CLUSter

EMC: Association for Promoting Electronics Technology – APTE (www.apte.org.ro)

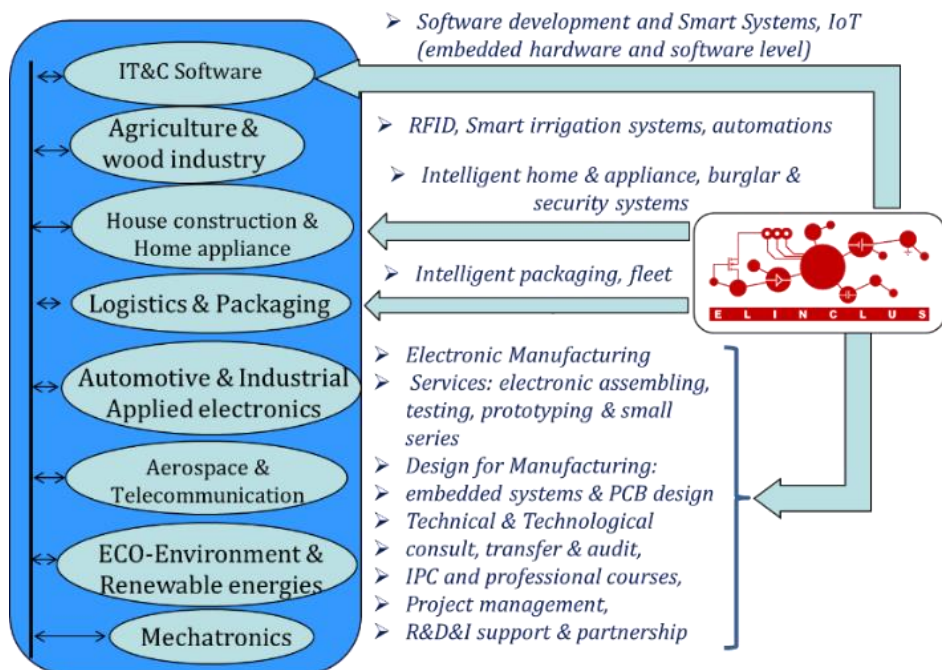
Founded 2011; 94 registered members

President: Prof. DHC. mult. Paul SVASTA, Ph.D.

Executive Manager: Lect. Eng. Bogdan Mihăilescu, Ph.D.



- Founding member of the Clusters Association from Romania, CLUSTERO - www.clustero.eu
- European Cluster Excellence Initiative Silver Label Certificate from ESCA since 2016
- Founding member of the IT Cluster Network from Romania comprised of 9 members
9: Transilvania IT Cluster, ALT – Braşov, Banat Software, Innovative Cluster Open Hub, INOMAR, **ELINCLUS**, ICT Oltenia, ICT Cluster Lower Danube şi Smart Alliance Cluster.
- Founding member of the regional Digital Innovation Hub – Smart e-Hub
<https://smarte-hub.eu/>



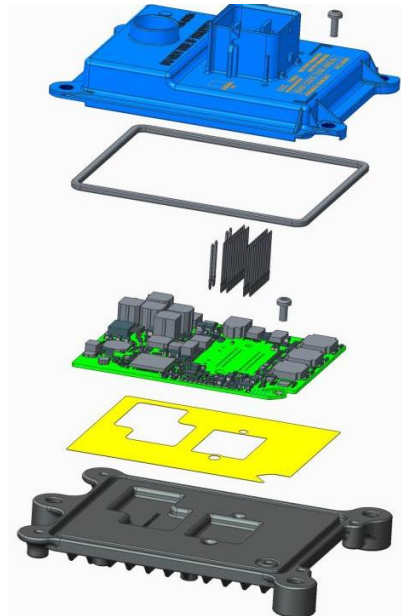
• **E-mail:** office@elinclus.ro **Web page:** www.elinclus.ro

ITEC Research Center

belongs to the Technical University of Cluj-Napoca having 25 researchers in Embedded Systems (electronics & software). ITEC can access the entire infrastructure of Technical University of Cluj-Napoca, resources from all other research centers and resources from Romanian University Alliance.

ITEC Competencies

- Circuit design: modeling, simulation and cross-simulation of electronic circuits (analog, digital, power, RF/EMI) & system design: modeling and simulation for electro-mechanical systems: power devices, actuators, mechatronics;
- HW Application design: fast-prototype design, PCB design for mass production, BOM/AVL design, DfM & DfT for embedded applications, power supplies, interface/signal conditioning boards;
- SW Application design: embedded control applications for OS and non-OS targets;
- TW Application design: testing and design of testing systems: SW and HW testing process, HiL and SiL, design of test-cases for SW;
- Training services: LabVIEW trainings, Embedded Systems trainings, TW and HiL operation;
- PCB DESIGN: DfX, SI and PI.



Contact

Information Technology in Electronics Research Center | Technical University of Cluj-Napoca
400027, G. Baritiu 26-28, Cluj-Napoca, Romania | E-Mail: gabriel.chindris@ael.utcluj.ro



I C S T M

Valahia University of Târgoviște

(www.valahia.ro)

***Institute of Multidisciplinary Research for
Science and Technology***

(www.icstm.valahia.ro)

The **Institute of Multidisciplinary Research for Science and Technology (ICSTM)** is a research structure within *Valahia University of Târgoviște*. Established in 2003, its *primary mission is to conduct advanced research*. In keeping with current developments in the responsible valorisation of research and the principles promoted by CoARA, the Institute recognises the *diversity of research contributions and their impact across multiple dimensions—scientific, technological, economic, social and educational*. At the same time, the Institute helps strengthen the scientific visibility of Valahia University of Târgoviște and *fosters a culture of responsible, open and collaborative research focused on sustainability, innovation and societal needs*.

The Institute brings together *multidisciplinary expertise* and currently has a *team of 17 members (14 research scientists and 3 research engineers)*. They carry out research, development and innovation (RDI) activities in fields including electrical engineering, electronics and communications, information technology, systems engineering, energy, environmental sciences, biotechnology, applied sciences, advanced materials, chemical engineering and sustainable development, in collaboration with the University's faculties, doctoral schools and administrative structures.

ICSTM *significantly expanded its RDI capacity* through a project implemented between 2010 and 2014 with non-reimbursable structural funding (POS-CCE-O221-ID916-SMIS-14687). The project funded the *construction and equipping of the current building*, which has an area of 7,250 square metres with A energy-efficiency rating. The investment amounted to approximately EUR 13 million, of which around 50% was allocated to advanced research equipment. Since its inauguration in October 2014, the entire infrastructure—including the building, technical installations, access routes and advanced research equipment—has been properly used and maintained, while also being expanded and diversified through numerous research and institutional development projects undertaken at Valahia University of Târgoviște. These projects have been financed through national funding sources (FDI, PFE, PNCDI III, PNCDI IV and other sources, including sponsorships and the University's own funds) and international funding programmes (Horizon 2020, Horizon Europe, EEA and Norway Grants, among others).

All laboratories and facilities within the Institute are *shared resources available to the entire academic community of Valahia University of Târgoviște*. Members of the University's 21 institutionally recognised research centres who implement RDI projects or

conduct research requiring advanced laboratory investigations, facilities for testing and piloting various installations, or other specific RDI activities may access and use ICSTM's equipment and facilities.

ICSTM is the main research facility of Valahia University of Târgoviște. It comprises 31 advanced research laboratories, three technological laboratories, ancillary facilities, four experimental platforms, administrative areas and spaces for disseminating research results (including an auditorium), as well as installations and other facilities dedicated to RDI activities. The infrastructure is also registered and presented on *EERTIS—Engage in the European Research and Technology Infrastructures System* - a European platform dedicated to promoting and facilitating access to research and technological infrastructures, equipment and services. Further details: <https://eertis.eu/erio-2300-000m-4240>.

ICSTM provides an enabling environment for research, development and innovation activities, the provision of RDI services, academic collaboration and partnerships with industry and the wider business community. Its infrastructure supports complex studies and experiments, advanced analyses, testing and materials characterisation, prototype development and technological validation. Although the Institute focuses primarily on applied research, it also actively supports fundamental research, interdisciplinary development, the training of early-career researchers and student involvement in scientific activities.



Contact: secretariat.icstm@valahia.ro, [+40-245-206109](tel:+40245206109)

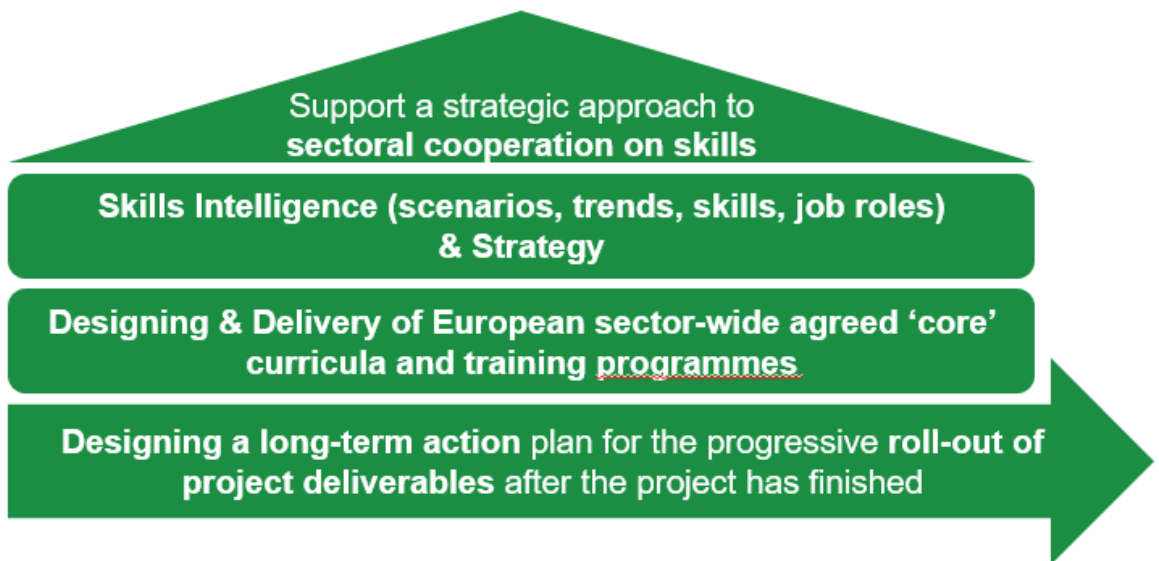
TRIEME Project

DigiTal & GRen Skills TowaRds FuturE of the MObility Ecosystem

TRIEME is a 4 year Erasmus+ funded project aimed at developing tools and activities to enhance skills and foster collaboration within the automotive sector, facilitating the transition towards a greener and more digital future. The project aligns with the European Pact for Skills and its respective large-scale Partnership, the Automotive Skills Alliance.

4-year **ERASMUS+ Blueprint** Project (2024 – 2028)

31 project partners from the **Automotive Skills Alliance** partnership



Support skills agenda in the Automotive-
Mobility Ecosystem through the Large-scale
Pact for Skills Partnership



**AUTOMOTIVE
SKILLS
ALLIANCE**

Contact details:

Bogdan MIHĂILESCU – bogdan.mihailescu@apte.org.ro

APTE

Wallachia eHUB

Drive innovation and digitalisation to growth

Free services offered by Wallachia eHUB for SME companies

SUPPORT TO FIND INVESTMENTS

TEST BEFORE INVEST

SKILLS DEVELOPMENT AND
PROFESSIONAL TRAINING IN
THE DIGITAL WORLD

CREATING DIGITAL
COMMUNITIES AND
NETWORKING

Through the Wallachia e-Hub project, we increase the digital capacity of SMEs and LPAs, in order to develop processes, products, digital services and interoperability, by offering specialized services based on advanced technologies such as AI, cyber security, robotics, mobility, location technologies (GIS), Building Information Modeling (BIM), etc.

With a total value of 3,172,262.50 euros, the Wallachia e-Hub project is financed by the Digital Europe Program (EC/101083410) - WeH and by the Increasing Intelligence, Digitization and Financial Instruments Program (POCIDIF/1147/2/1/161799), being implemented between January 1, 2023 and December 31, 2025.

Project Coordinator:



Project Partners:



Contact details:

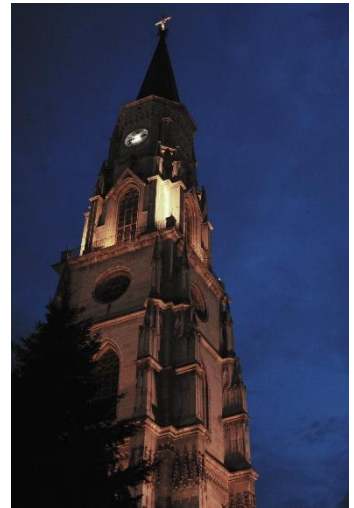
Bogdan MIHĂILESCU – bogdan.mihailescu@apte.org.ro

If you fulfil the eligibility conditions please apply here:



Cluj-Napoca welcomes to the IEEE 33rd International Symposium for Design and Technology in Electronics Packaging!

On behalf of the Technical University of Cluj-Napoca and the IEEE Hungary and Romania Section EPS & NTC Joint Chapter, it is our great pleasure to announce the **IEEE 33rd International Symposium for Design and Technology in Electronics Packaging (SIITME)**, to be held in Cluj-Napoca, Romania, between 27 and 30 October 2027.



For more than three decades, SIITME has brought together researchers, academics, industry professionals, and students from across Europe and beyond, providing a valuable forum for the exchange of scientific knowledge and technological innovation in the fields of semiconductor devices, integrated circuits, microelectronics, packaging technologies, microsystems, and emerging electronic technologies.

We are delighted to host next edition in Cluj-Napoca, a city renowned for its academic excellence, rich historical heritage, vibrant innovation ecosystem, and dynamic student community. As one of Central and Eastern Europe's leading centers for education and technology, Cluj-Napoca provides an inspiring environment for scientific exchange, professional networking, and the development of future collaborations.

We wish you a productive, intellectually stimulating, and enjoyable conference experience and hope that the discussions, ideas, and connections established during SIITME 2027 will lead to lasting partnerships and new opportunities for scientific and technological progress.

Gabriel CHINDRIȘ Ph. D.

*Associate Professor, Technical University of Cluj-Napoca
Chair, Hungary and Romania Section EPS&NTC Joint Chapter*





SIITME 2027

IEEE 33rd International Symposium for Design and Technology in Electronic Packaging

Conference and Exhibition | Cluj-Napoca | Romania | October 27th – 30th 2027



Call for Papers

The organising committee of SIITME 2027 kindly invites you to submit an abstract/paper to the IEEE 33rd International Symposium for Design and Technology in Electronic Packaging.

Topics

- Emerging Topics in Advanced Packaging
- New Components and Manufacturing Technologies
- Printed Electronics, Smart Textiles and Healthcare
- Sensors, Actuators and Microsystems
- Nanomaterials, Nanoelectronics and Nanotechnology
- Embedded Systems, Robotics and Artificial Intelligence
- Power Electronics and Thermal Management
- Smart Grid and Renewable Energy
- Virtual Prototyping and System Validation;

Venue

Cluj-Napoca, Romania

October 26th – 30th 2027



Calendar

Submission of abstracts:

20th of May 2027

Abstract acceptance:

30th of June 2027

Submission of papers:

1st of September 2027

Registration deadline:

20th of September 2027



University
Politehnica of
Bucharest





ARC Braşov

